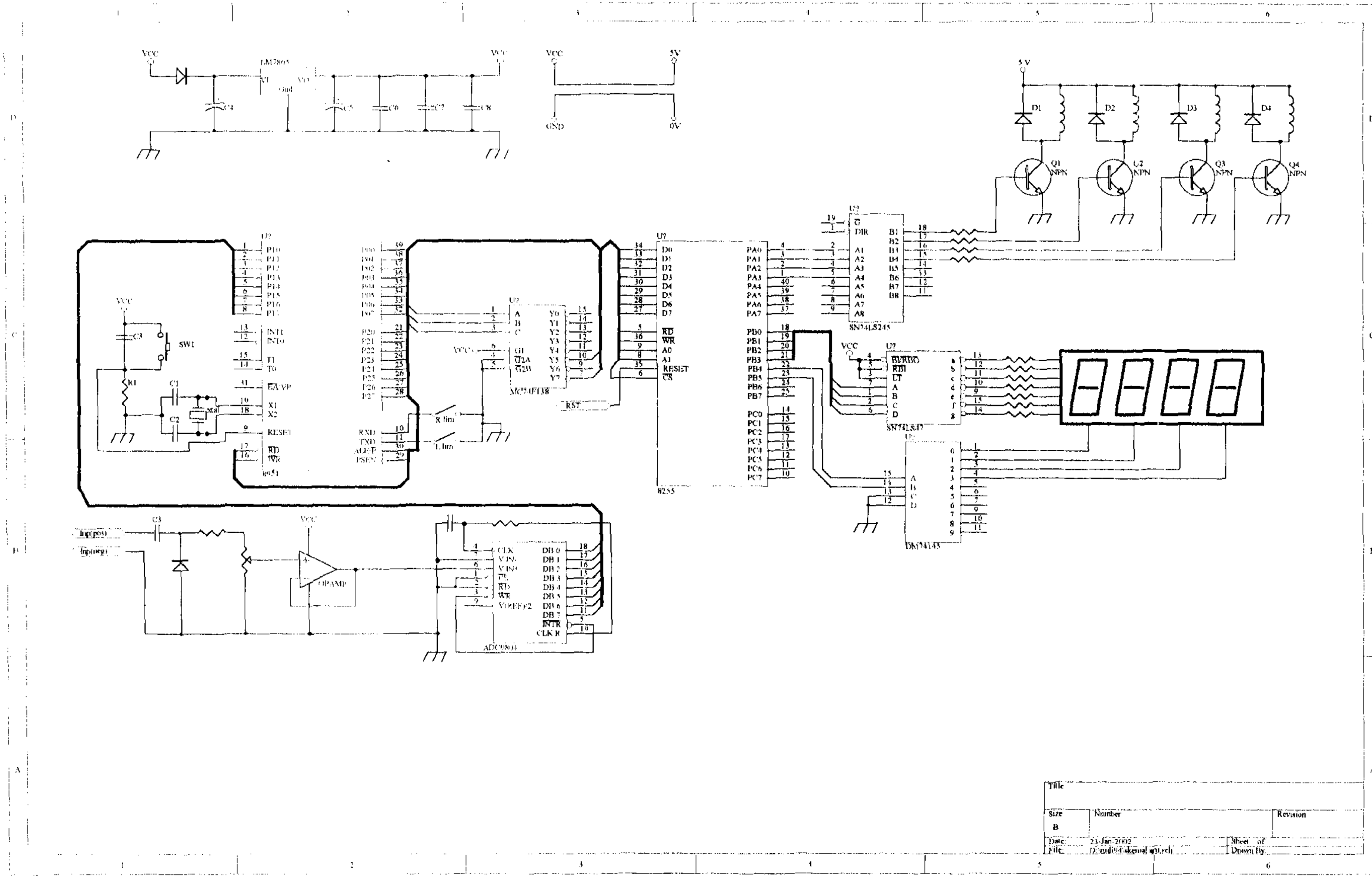
LAMPIRAN



LM7805
VCC
GND
5V
0V
SN74LS245
SN74LS47
DM74145
8255
MC74HCT138
8051
ADC0804
OPAMP
SW1
Xtal
R lim
L lim
RST
Inp(pos)
Inp(neg)
Q1 NPN
Q2 NPN
Q3 NPN
Q4 NPN
D1
D2
D3
D4
Title
Size
B
Number
Revision
Date:
23-Jan-2002
File:
Sheet of
Drawn By:

```
PORT_A          EQU 2000H
PORT_B          EQU 2001H
PORT_C          EQU 2002H
CONTROL_REG     EQU 2003H
DIGIT1          EQU 21H
DIGIT2          EQU 22H
DIGIT3          EQU 23H
DIGIT4          EQU 24H
INPUT           EQU 30H
COUNTER         EQU 31H
TEMPORARY       EQU 32H
BUFFER          EQU 33H


        ORG 0000H
        AJMP MAIN

MAIN:       ACALL INIT_PPI


AGAIN:  MOV A,P1
        MOV BUFFER,A
        MOV INPUT,A

        CLR C

        MOV A,BUFFER

        SUBB A,#100
        JNC CONTINUE2

        JNB F0,CCW
        ACALL PUTAR_CW
        SJMP CONTINUE

CCW:        ACALL  PUTAR_CCW

CONTINUE:       MOV COUNTER,#2FH
REFRESH:        DJNZ COUNTER,REFRESH
        SJMP AGAIN
CONTINUE2:      MOV DPTR,#PORT_A
        MOV A,#00010000B
        MOVX @DPTR,A
        MOV COUNTER,#2FH
REFRESH2:       DJNZ COUNTER,REFRESH
        SJMP AGAIN
```

```
EXIT:           NOP
                SJMP EXIT
;--------------------------------------------------------------------------
INIT_PPI:           PUSH DPH
                PUSH DPL
                MOV DPTR,#CONTROL_REG
                MOV A,#80H
                MOVX @DPTR,A
                POP DPL
                POP DPH
                RET

DELAY_LOOP:         PUSH DPH
                PUSH DPL
                PUSH ACC
                PUSH PSW

DEL_LOOP:           DEC R1
                NOP
                NOP
                NOP
                CJNE R1,#0H,DEL_LOOP

                POP PSW
                POP ACC
                POP DPL
                POP DPH
                RET


DELAY_5S:           PUSH DPH
                PUSH DPL
                PUSH ACC
                PUSH PSW

                MOV R7,#0FH
DEL2:               MOV A,#0FFH
DEL3:               MOV B,#0FFH
                DJNZ B,$
                DJNZ ACC,DEL3
                DJNZ R7,DEL2

                POP PSW
                POP ACC
                POP DPL
                POP DPH
```

```
            RET

DELAY_2S:       PUSH DPH
            PUSH DPL
            PUSH ACC
            PUSH PSW

            MOV R7,#100  ;7H
DEL4:           MOV A,#5     ;5H
DEL5:           MOV B,#3     ;3H
            DJNZ B,$
            DJNZ ACC,DEL5
            DJNZ R7,DEL4

            POP PSW
            POP ACC
            POP DPL
            POP DPH
            RET
;--------------------------------------------------------------------------
PUTAR_CCW:      PUSH DPH
            PUSH DPL

            MOV DPTR,#PORT_A
            MOV A,#01H
            MOVX @DPTR,A

            MOV A,#2H
            MOVX @DPTR,A

            MOV A,#4H
            MOVX @DPTR,A

            MOV A,#8H
            MOVX @DPTR,A

            MOV A,#0
            MOVX @DPTR,A

            POP DPL
            POP DPH
            RET
;--------------------------------------------------------------------------
PUTAR_CW:       PUSH DPH
            PUSH DPL
```

```
        MOV DPTR,#PORT_A

        MOV A,#8H
        MOVX @DPTR,A

        MOV A,#4H
        MOVX @DPTR,A

        MOV A,#2H
        MOVX @DPTR,A

        MOV A,#1H
        MOVX @DPTR,A


        MOV A,#0
        MOVX @DPTR,A
        POP DPL
        POP DPH
        RET

;------------------------------------------------------------------------
DELAY_1S:     PUSH DPH
        PUSH DPL
        PUSH ACC
        PUSH PSW

        MOV R7,#2FH
DEL44:      MOV A,#5H
DEL55:      MOV B,#3H
        DJNZ B,$
        DJNZ ACC,DEL55
        DJNZ R7,DEL44

        POP PSW
        POP ACC
        POP DPL
        POP DPH
        RET
;------------------------------------------------------------------------
        END
```

tures

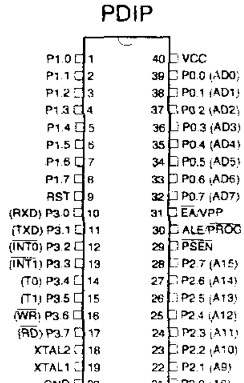
- npatible with MCS-51™ Products
- Bytes of In-System Reprogrammable Flash Memory
- Endurance: 1,000 Write/Erase Cycles
- ly Static Operation: 0 Hz to 24 MHz
- ee-level Program Memory Lock
- x 8-bit Internal RAM
- Programmable I/O Lines
- 16-bit Timer/Counters
- Interrupt Sources
- grammable Serial Channel
- v-power Idle and Power-down Modes

cription

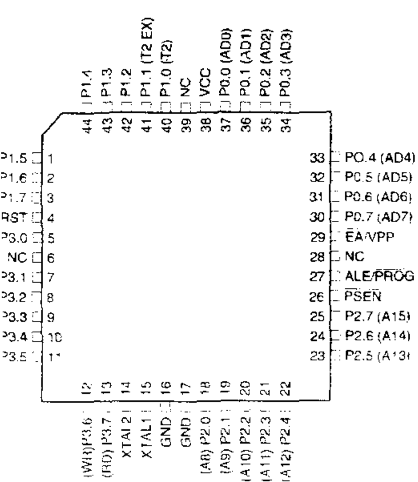
AT89C51 is a low-power, high-performance CMOS 8-bit microcomputer with 4K of Flash programmable and erasable read only memory (PEROM). The device nufactured using Atmel's high-density nonvolatile memory technology and is atible with the industry-standard MCS-51 instruction set and pinout. The on-chip allows the program memory to be reprogrammed in-system or by a conven- nonvolatile memory programmer. By combining a versatile 8-bit CPU with Flash monolithic chip, the Atmel AT89C51 is a powerful microcomputer which provides nly-flexible and cost-effective solution to many embedded control applications.

Configurations

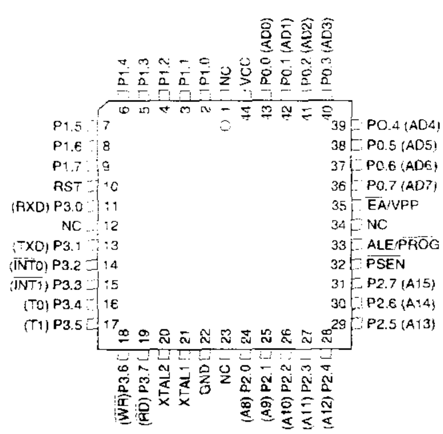
PDIP



PQFP/TQFP



PLCC

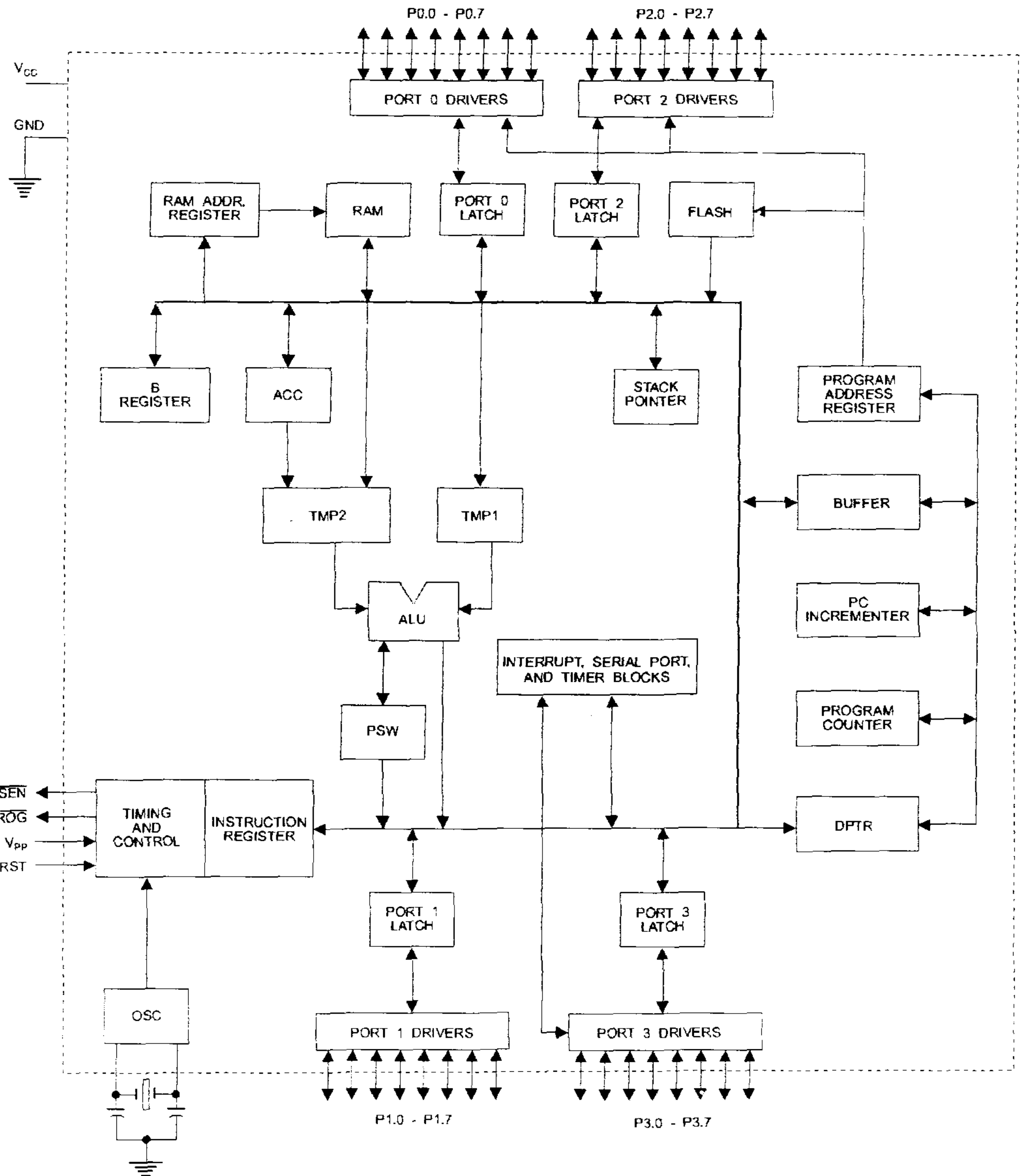


8-bit Microcontroller with 4K Bytes Flash

AT89C51

Rev. 0265G–02/00

ock Diagram


P0.0 - P0.7
P2.0 - P2.7
VCC
GND
PORT 0 DRIVERS
PORT 2 DRIVERS
RAM ADDR. REGISTER
RAM
PORT 0 LATCH
PORT 2 LATCH
FLASH
B REGISTER
ACC
STACK POINTER
PROGRAM ADDRESS REGISTER
BUFFER
TMP2
TMP1
ALU
PC INCREMENTER
INTERRUPT, SERIAL PORT, AND TIMER BLOCKS
PSW
PROGRAM COUNTER
SEN
ROG
VPP
RST
TIMING AND CONTROL
INSTRUCTION REGISTER
DPTR
PORT 1 LATCH
PORT 3 LATCH
OSC
PORT 1 DRIVERS
PORT 3 DRIVERS
P1.0 - P1.7
P3.0 - P3.7

scription (Continued)

AT89C51 provides the following standard features: 4 es of Flash, 128 bytes of RAM, 32 I/O lines, two 16-bit r/counters, a five vector two-level interrupt architec- a full duplex serial port, on-chip oscillator and clock itry. In addition, the AT89C51 is designed with static for operation down to zero frequency and supports software selectable power saving modes. The Idle e stops the CPU while allowing the RAM, timer/count- serial port and interrupt system to continue function- The Power Down Mode saves the RAM contents but es the oscillator disabling all other chip functions until next hardware reset.

Description

ly voltage.

nd.

)

0 is an 8-bit open drain bidirectional I/O port. As an ut port each pin can sink eight TTL inputs. When 1s written to port 0 pins, the pins can be used as high-im- nce inputs.

0 may also be configured to be the multiplexed low- address/data bus during accesses to external pro- and data memory. In this mode P0 has internal pul-

0 also receives the code bytes during Flash program- , and outputs the code bytes during program verifica- External pullups are required during program verifica-

1 is an 8-bit bidirectional I/O port with internal pullups. Port 1 output buffers can sink/source four TTL inputs. n 1s are written to Port 1 pins they are pulled high by nternal pullups and can be used as inputs. As inputs, 1 pins that are externally being pulled low will source nt (I_{IL}) because of the internal pullups.

1 also receives the low-order address bytes during programming and program verification.

2

2 is an 8-bit bidirectional I/O port with internal pullups. Port 2 output buffers can sink/source four TTL inputs. n 1s are written to Port 2 pins they are pulled high by nternal pullups and can be used as inputs. As inputs, 2 pins that are externally being pulled low will source nt (I_{IL}) because of the internal pullups.

2 emits the high-order address byte during fetches external program memory and during accesses to nal data memory that use 16-bit addresses (MOVX @ DPTR). In this application it uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

Port 3

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features of the AT89C51 as listed below:

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{\text{INT0}}$ (extenal interrupt 0)
P3.3	$\overline{\text{INT1}}$ (extenal interrupt 1)
P3.4	T0 (timer 0 extenal input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{\text{WR}}$ (extenal data memory write strobe)
P3.7	$\overline{\text{RD}}$ (external data memory read strobe)

Port 3 also receives some control signals for Flash programming and programming verification.

RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

ALE/$\overline{\text{PROG}}$

Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during Flash programming.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcrontroller is in external execution mode.

$\overline{\text{PSEN}}$

Program Store Enable is the read strobe to external program memory.

(continued)

ı Description (Continued)

ːn the AT89C51 is executing code from external pro-
ı memory, PSEN is activated twice each machine cy-
except that two PSEN activations are skipped during
ı access to external data memory.

PP

rnal Access Enable. EA must be strapped to GND in
r to enable the device to fetch code from external pro-
ı memory locations starting at 0000H up to FFFFH.
, however, that if lock bit 1 is programmed, EA will be
nally latched on reset.

hould be strapped to V_{CC} for internal program execu-
.

pin also receives the 12-volt programming enable
ge (V_{PP}) during Flash programming, for parts that re-
12-volt V_{PP}.

.1

to the inverting oscillator amplifier and input to the
nal clock operating circuit.

2

ut from the inverting oscillator amplifier.

cillator Characteristics

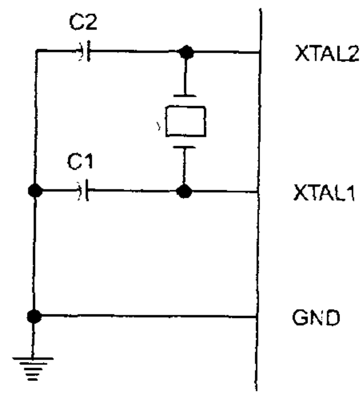
.1 and XTAL2 are the input and output, respectively,
inverting amplifier which can be configured for use
ı on-chip oscillator, as shown in Figure 1. Either a
z crystal or ceramic resonator may be used. To drive
evice from an external clock source, XTAL2 should
ft unconnected while XTAL1 is driven as shown in
e 2. There are no requirements on the duty cycle of
xternal clock signal, since the input to the internal
ing circuitry is through a divide-by-two flip-flop, but
num and maximum voltage high and low time specifi-
ıs must be observed.

Mode

ɜ mode, the CPU puts itself to sleep while all the on-
peripherals remain active. The mode is invoked by
are. The content of the on-chip RAM and all the spe-
unctions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

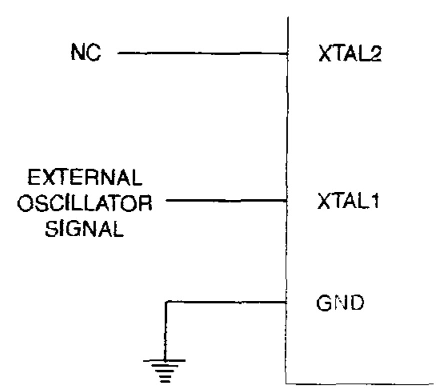
It should be noted that when idle is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hard-

Figure 1. Oscillator Connections



Notes: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 2. External Clock Drive Configuration



tus of External Pins During Idle and Power Down

le	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
	Internal	1	1	Data	Data	Data	Data
	External	1	1	Float	Data	Address	Data
ver Down	Internal	0	0	Data	Data	Data	Data
ver Down	External	0	0	Float	Data	Data	Data

ıre inhibits access to internal RAM in this event, but ac-ss to the port pins is not inhibited. To eliminate the pos-ıility of an unexpected write to a port pin when Idle is minated by reset, the instruction following the one that vokes Idle should not be one that writes to a port pin or external memory.

ower Down Mode

the power down mode the oscillator is stopped, and the struction that invokes power down is the last instruction ecuted. The on-chip RAM and Special Function Regis-s retain their values until the power down mode is termi-ted. The only exit from power down is a hardware reset. eset redefines the SFRs but does not change the on-ip RAM. The reset should not be activated before VCC is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Program Memory Lock Bits

On the chip are three lock bits which can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the table below:

When lock bit 1 is programmed, the logic level at the $\overline{EA}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value, and holds that value until reset is activated. It is necessary that the latched value of $\overline{EA}$ be in agreement with the current logic level at that pin in order for the device to function properly.

ɔck Bit Protection Modes

Program Lock Bits				
	LB1	LB2	LB3	Protection Type
1	U	U	U	No program lock features.
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the Flash is disabled.
3	P	P	U	Same as mode 2, also verify is disabled.
4	P	P	P	Same as mode 3, also external execution is disabled.

·ogramming the Flash

ə AT89C51 is normally shipped with the on-chip Flash mory array in the erased state (that is, contents = FFH) d ready to be programmed. The programming interface cepts either a high-voltage (12-volt) or a low-voltage ;c) program enable signal. The low voltage program-ıg mode provides a convenient way to program the 89C51 inside the user's system, while the high-voltage gramming mode is compatible with conventional third ty Flash or EPROM programmers.

ə AT89C51 is shipped with either the high-voltage or -voltage programming mode enabled. The respective -side marking and device signature codes are listed in following table.

	VPP = 12 V	VPP = 5 V
ɔp-Side Mark	AT89C51 xxxx yyww	AT89C51 xxxx-5 yyww
gnature	(030H)=1EH (031H)=51H (032H)=FFH	(030H)=1EH (031H)=51H (032H)=05H

The AT89C51 code memory array is programmed byte-by-byte in either programming mode. *To program any non-blank byte in the on-chip Flash Memory, the entire memory must be erased using the Chip Erase Mode.*

Programming Algorithm: Before programming the AT89C51, the address, data and control signals should be set up according to the Flash programming mode table and Figures 3 and 4. To program the AT89C51, take the following steps.

1. Input the desired memory location on the address lines.
2. Input the appropriate data byte on the data lines.
3. Activate the correct combination of control signals.
4. Raise $\overline{EA}$/VPP to 12 V for the high-voltage programming mode.
5. Pulse ALE/$\overline{PROG}$ once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 1.5 ms. Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

$\overline{\text{Data}}$ Polling: The AT89C51 features $\overline{\text{Data}}$ Polling to indicate the end of a write cycle. During a write cycle, an at-

(continued)

rogramming the Flash (Continued)

mpted read of the last byte written will result in the com-ement of the written datum on PO.7. Once the write cy-e has been completed, true data are valid on all outputs, d the next cycle may begin. Data Polling may begin any ne after a write cycle has been initiated.

eady/Busy: The progress of byte programming can so be monitored by the RDY/BSY output signal. P3.4 is lled low after ALE goes high during programming to in-cate BUSY. P3.4 is pulled high again when program-ng is done to indicate READY.

ogram Verify: If lock bits LB1 and LB2 have not been ogrammed, the programmed code data can be read ck via the address and data lines for verification. The k bits cannot be verified directly. Verification of the lock s is achieved by observing that their features are en-led.

ip Erase: The entire Flash array is erased electrically using the proper combination of control signals and by lding ALE/PROG low for 10 ms. The code array is writ-n with all "1"s. The chip erase operation must be exe-ted before the code memory can be re-programmed.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H,

031H, and 032H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(030H) = 1EH indicates manufactured by Atmel
(031H) = 51H indicates 89C51
(032H) = FFH indicates 12 V programming
(032H) = 05H indicates 5 V programming

Programming Interface

Every code byte in the Flash array can be written and the entire array can be erased by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

All major programming vendors offer worldwide support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

lash Programming Modes

lode		RST	PSEN	ALE/ PROG	EA/ VPP	P2.6	P2.7	P3.6	P3.7
Vrite Code Data		H	L	⌐_/¬	H/12V(1)	L	H	H	H
ead Code Data		H	L	H	H	L	L	H	H
Vrite Lock	Bit - 1	H	L	⌐_/¬	H/12V	H	H	H	H
	Bit - 2	H	L	⌐_/¬ (2)	H/12V	H	H	L	L
	Bit - 3	H	L	⌐_/¬	H/12V	H	L	H	L
hip Erase		H	L	⌐_/¬	H/12V	H	L	L	L
ead Signature yte		H	L	H	H	L	L	L	L

es: 1. The signature byte at location 032H designates whether V_{PP} = 12 V or V_{PP} = 5 V should be used to enable programming.

2. Chip Erase requires a 10 ms PROG pulse.

ure 3. Programming the Flash

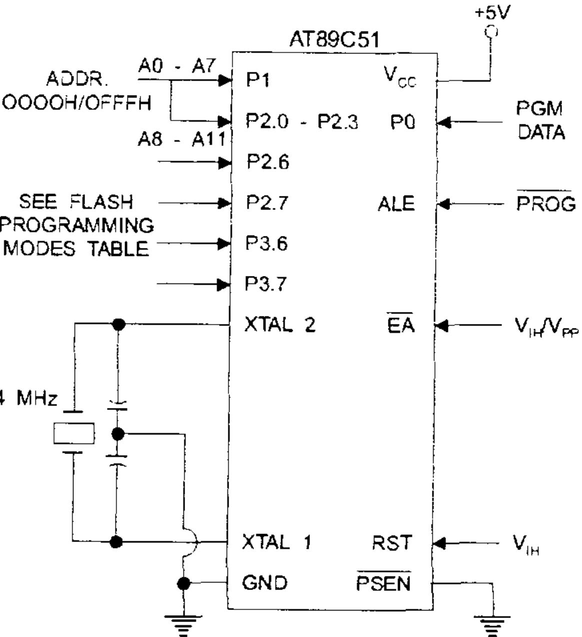
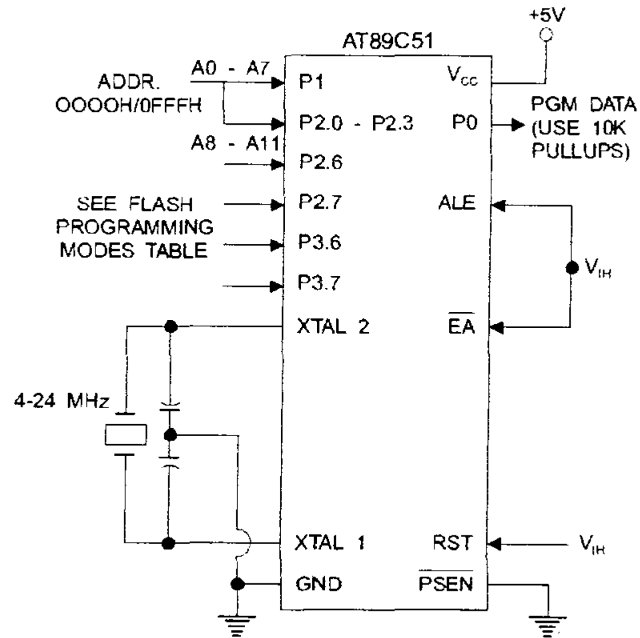


Figure 4. Verifying the Flash



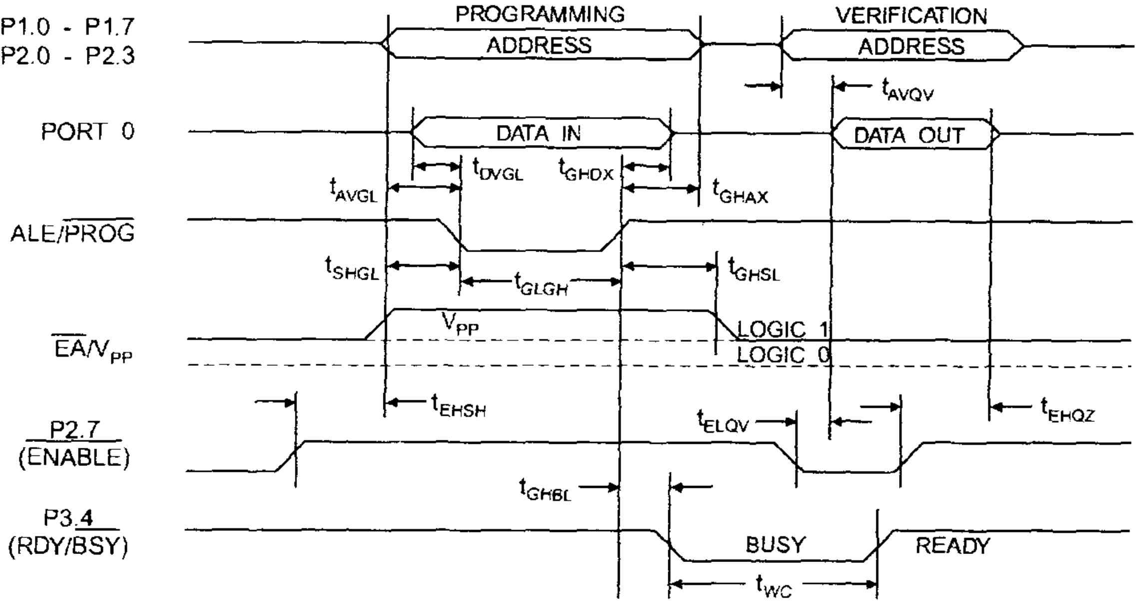
ash Programming and Verification Characteristics

= 21°C to 27°C, V_{CC} = 5.0 ± 10%

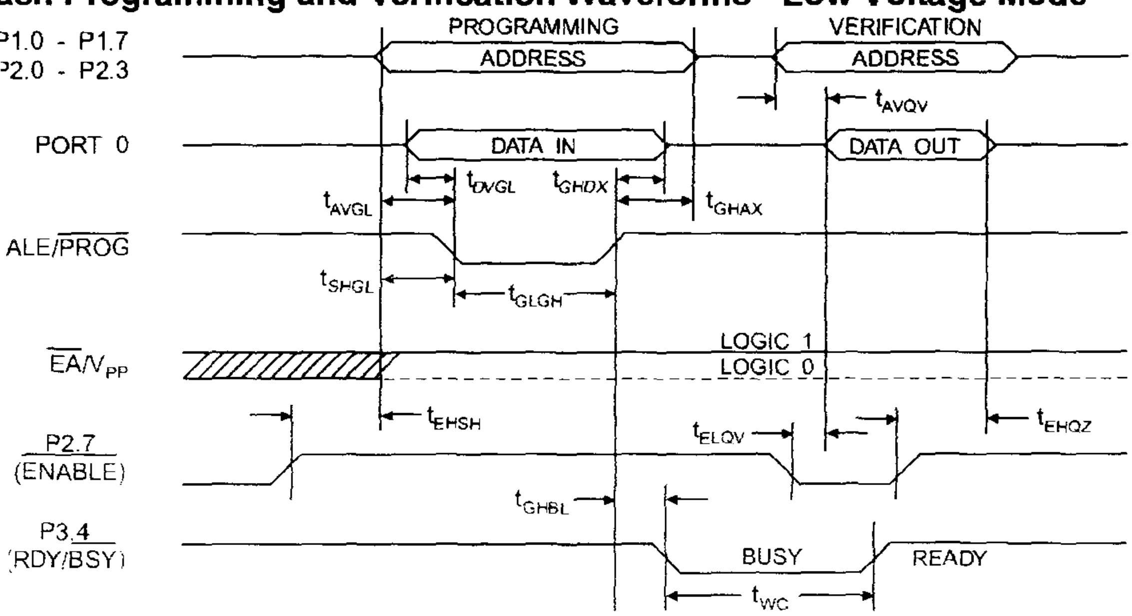
ymbol	Parameter	Min	Max	Units
p[1]	Programming Enable Voltage	11.5	12.5	V
[1]	Programming Enable Current		1.0	mA
CLCL	Oscillator Frequency	4	24	MHz
/GL	Address Setup to PROG Low	48tCLCL		
HAX	Address Hold After PROG	48tCLCL		
/GL	Data Setup to PROG Low	48tCLCL		
HDX	Data Hold After PROG	48tCLCL		
HSH	P2.7 (ENABLE) High to VPP	48tCLCL		
HGL	VPP Setup to PROG Low	10		µs
HSL[1]	VPP Hold After PROG	10		µs
GH	PROG Width	1	110	µs
/QV	Address to Data Valid		48tCLCL	
QV	ENABLE Low to Data Valid		48tCLCL	
IQV	Data Float After ENABLE	0	48tCLCL	
HBL	PROG High to BUSY Low		1.0	µs
:	Byte Write Cycle Time		2.0	ms

: 1. Only used in 12-volt programming mode.

ash Programming and Verification Waveforms - High Voltage Mode



ash Programming and Verification Waveforms - Low Voltage Mode



osolute Maximum Ratings*

Operating Temperature..................	-55°C to +125°C
Storage Temperature.....................	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0 V to +7.0 V
aximum Operating Voltage	6.6 V
C Output Current.......................................	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

C. Characteristics

= -40°C to 85°C, V_{CC} = 5.0 V ± 20% (unless otherwise noted)

mbol	Parameter	Condition	Min	Max	Units
	Input Low Voltage	(Except $\overline{EA}$)	-0.5	0.2 V_{CC}-0.1	V
1	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC}-0.3	V
H	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
1	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
L	Output Low Voltage[(1)] (Ports 1,2,3)	I_{OL} = 1.6 mA		0.45	V
L1	Output Low Voltage[(1)] (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.45	V
H	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, V_{CC} = 5 V ± 10%	2.4		V
		I_{OH} = -25 µA	0.75 V_{CC}		V
		I_{OH} = -10 µA	0.9 V_{CC}		V
H1	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA, V_{CC} = 5 V ± 10%	2.4		V
		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45 V		-50	µA
	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2 V		-650	µA
	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
ST	Reset Pulldown Resistor		50	300	KΩ
	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
	Power Supply Current	Active Mode, 12 MHz		20	mA
		Idle Mode, 12 MHz		5	mA
	Power Down Mode[(2)]	V_{CC} = 6 V		100	µA
		V_{CC} = 3 V		40	µA

s: 1. Under steady state (non-transient) conditions. I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 10 mA
Maximum I_{OL} per 8-bit port:
Port 0: 26 mA
Ports 1,2, 3: 15 mA
Maximum total IOL for all output pins: 71 mA
If IOL exceeds the test condition, VOL may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum VCC for Power Down is 2 V.

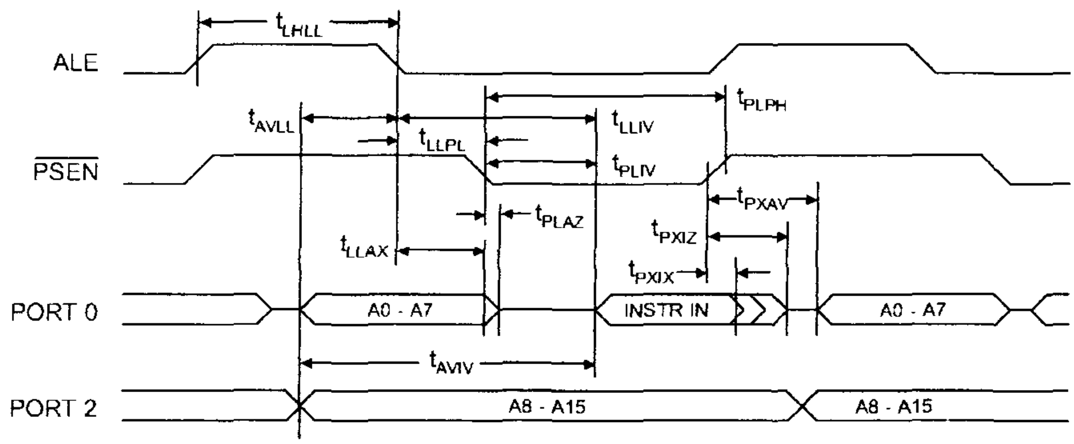
.C. Characteristics

nder Operating Conditions; Load Capacitance for Port 0, ALE/$\overline{PROG}$, and $\overline{PSEN}$ = 100 pF; Load Capacitance for all er outputs = 80 pF)

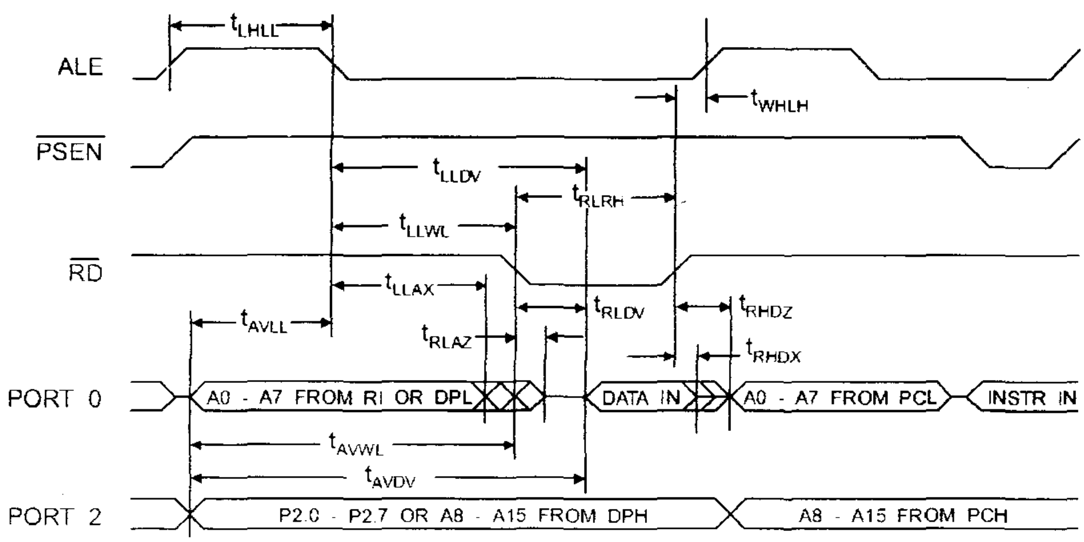
xternal Program and Data Memory Characteristics

ymbol	Parameter	12 MHz Oscillator		16 to 24 MHz Oscillator		Units
		Min	Max	Min	Max	
/tCLCL	Oscillator Frequency			0	24	MHz
HLL	ALE Pulse Width	127		2tCLCL-40		ns
VLL	Address Valid to ALE Low	28		tCLCL-13		ns
LAX	Address Hold After ALE Low	48		tCLCL-20		ns
LIV	ALE Low to Valid Instruction In		233		4tCLCL-65	ns
LPL	ALE Low to $\overline{PSEN}$ Low	43		tCLCL-13		ns
LPH	$\overline{PSEN}$ Pulse Width	205		3tCLCL-20		ns
LIV	$\overline{PSEN}$ Low to Valid Instruction In		145		3tCLCL-45	ns
XIX	Input Instruction Hold After $\overline{PSEN}$	0		0		ns
XIZ	Input Instruction Float After $\overline{PSEN}$		59		tCLCL-10	ns
XAV	$\overline{PSEN}$ to Address Valid	75		tCLCL-8		ns
VIV	Address to Valid Instruction In		312		5tCLCL-55	ns
LAZ	$\overline{PSEN}$ Low to Address Float		10		10	ns
LRH	$\overline{RD}$ Pulse Width	400		6tCLCL-100		ns
VLWH	$\overline{WR}$ Pulse Width	400		6tCLCL-100		ns
LDV	$\overline{RD}$ Low to Valid Data In		252		5tCLCL-90	ns
HDX	Data Hold After $\overline{RD}$	0		0		ns
HDZ	Data Float After $\overline{RD}$		97		2tCLCL-28	ns
DV	ALE Low to Valid Data In		517		8tCLCL-150	ns
VDV	Address to Valid Data In		585		9tCLCL-165	ns
WL	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	200	300	3tCLCL-50	3tCLCL+50	ns
VWL	Address to $\overline{RD}$ or $\overline{WR}$ Low	203		4tCLCL-75		ns
VWX	Data Valid to $\overline{WR}$ Transition	23		tCLCL-20		ns
VWH	Data Valid to $\overline{WR}$ High	433		7tCLCL-120		ns
HQX	Data Hold After $\overline{WR}$	33		tCLCL-20		ns
LAZ	$\overline{RD}$ Low to Address Float		0		0	ns
HLH	$\overline{RD}$ or $\overline{WR}$ High to ALE High	43	123	tCLCL-20	tCLCL+25	ns

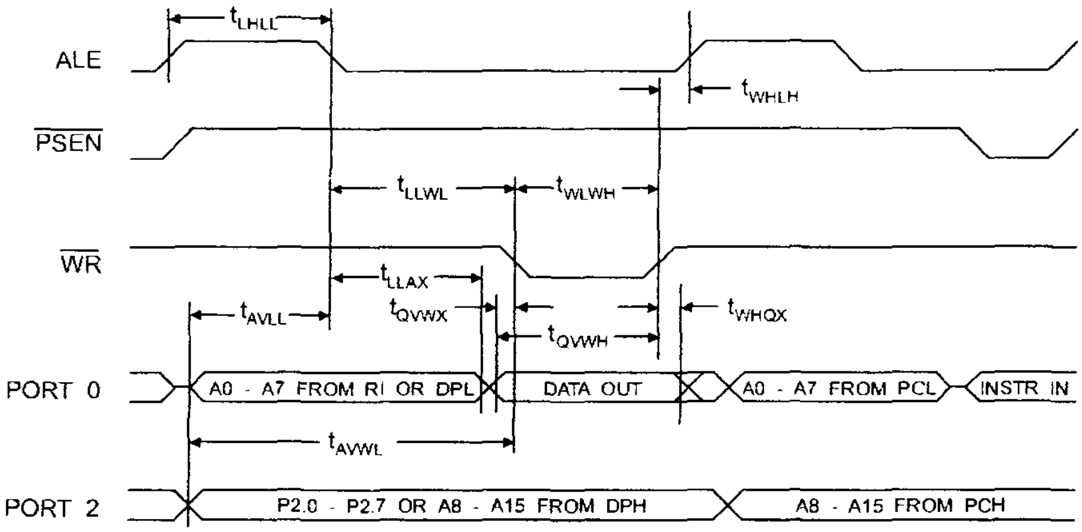
xternal Program Memory Read Cycle



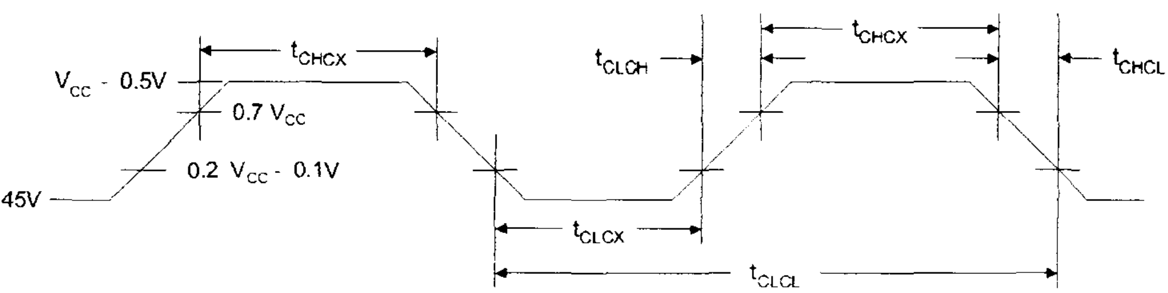
xternal Data Memory Read Cycle



xternal Data Memory Cycle



ternal Clock Drive Waveforms



ternal Clock Drive

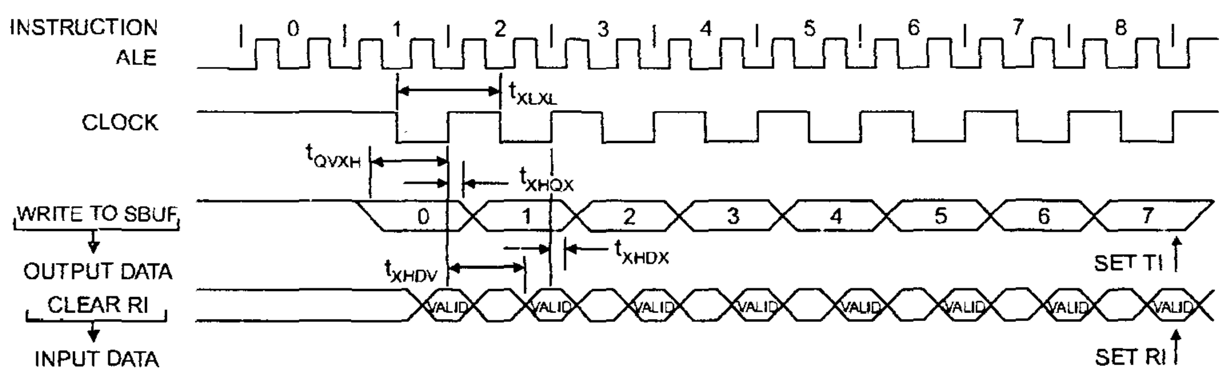
mbol	Parameter	Min	Max	Units
CLCL	Oscillator Frequency	0	24	MHz
.CL	Clock Period	41.6		ns
ICX	High Time	15		ns
.CX	Low Time	15		ns
CH	Rise Time		20	ns
ICL	Fall Time		20	ns

erial Port Timing: Shift Register Mode Test Conditions

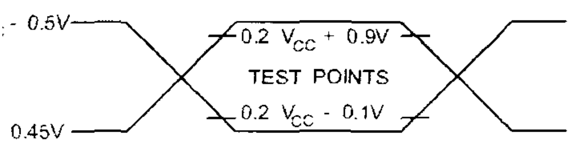
cc = 5.0 V ± 20%; Load Capacitance = 80 pF)

ymbol	Parameter	12 MHz Osc Min	12 MHz Osc Max	Variable Oscillator Min	Variable Oscillator Max	Units
LXL	Serial Port Clock Cycle Time	1.0		12tCLCL		µs
QVXH	Output Data Setup to Clock Rising Edge	700		10tCLCL-133		ns
HQX	Output Data Hold After Clock Rising Edge	50		2tCLCL-33		ns
HDX	Input Data Hold After Clock Rising Edge	0		0		ns
HDV	Clock Rising Edge to Input Data Valid		700		10tCLCL-133	ns

iift Register Mode Timing Waveforms

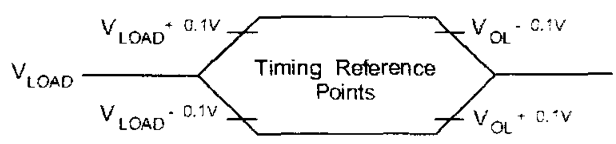


: Testing Input/Output Waveforms[1]



e: 1. AC Inputs during testing are driven at V_{CC} - 0.5 V for a logic 1 and 0.45 V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

Float Waveforms[1]



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

rdering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
12	5 V ± 20%	AT89C51-12AC AT89C51-12JC AT89C51-12PC AT89C51-12QC	44A 44J 40P6 44Q	Commercial (0°C to 70°C)
		AT89C51-12AI AT89C51-12JI AT89C51-12PI AT89C51-12QI	44A 44J 40P6 44Q	Industrial (-40°C to 85°C)
		AT89C51-12AA AT89C51-12JA AT89C51-12PA AT89C51-12QA	44A 44J 40P6 44Q	Automotive (-40°C to 125°C)
	5 V ± 10%	AT89C51-12DM AT89C51-12LM	40D6 44L	Military (-55°C to 125°C)
		AT89C51-12DM/883 AT89C51-12LM/883	40D6 44L	Military/883C Class B, Fully Compliant (-55°C to 125°C)
16	5 V ± 20%	AT89C51-16AC AT89C51-16JC AT89C51-16PC AT89C51-16QC	44A 44J 40P6 44Q	Commercial (0°C to 70°C)
		AT89C51-16AI AT89C51-16JI AT89C51-16PI AT89C51-16QI	44A 44J 40P6 44Q	Industrial (-40°C to 85°C)
		AT89C51-16AA AT89C51-16JA AT89C51-16PA AT89C51-16QA	44A 44J 40P6 44Q	Automotive (-40°C to 125°C)
20	5 V ± 20%	AT89C51-20AC AT89C51-20JC AT89C51-20PC AT89C51-20QC	44A 44J 40P6 44Q	Commercial (0°C to 70°C)
		AT89C51-20AI AT89C51-20JI AT89C51-20PI AT89C51-20QI	44A 44J 40P6 44Q	Industrial (-40°C to 85°C)

dering Information

peed MHz)	Power Supply	Ordering Code	Package	Operation Range
24	5 V ± 20%	AT89C51-24AC AT89C51-24JC AT89C51-24PC AT89C51-24QC	44A 44J 44P6 44Q	Commercial (0°C to 70°C)
		AT89C51-24AI AT89C51-24JI AT89C51-24PI AT89C51-24QI	44A 44J 44P6 44Q	Industrial (-40°C to 85°C)

	Package Type
\	44 Lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
)6	40 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
l	44 Lead, Plastic J-Leaded Chip Carrier (PLCC)
.	44 Pad, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
'6	40 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
l	44 Lead, Plastic Gull Wing Quad Flatpack (PQFP)

National Semiconductor Corporation

ADC0801, ADC0802, ADC0803, ADC0804, ADC0805 8-Bit μP Compatible A/D Converters

General Description

The ADC0801, ADC0802, ADC0803, ADC0804 and ADC0805 are CMOS 8-bit successive approximation A/D converters that use a differential potentiometric ladder—similar to the 256R products. These converters are designed to allow operation with the NSC800 and INS8080A derivative control bus with TRI-STATE® output latches directly driving the data bus. These A/Ds appear like memory locations or I/O ports to the microprocessor and no interfacing logic is needed.

Differential analog voltage inputs allow increasing the common-mode rejection and offsetting the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding any smaller analog voltage span to the full 8 bits of resolution.

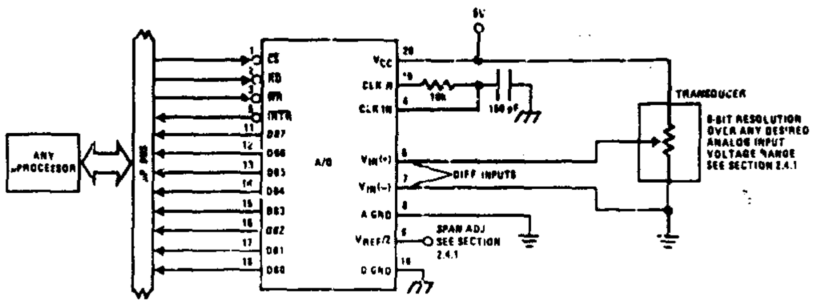
Features

- Compatible with 8080 μP derivatives—no interfacing logic needed - access time - 135 ns
- Easy interface to all microprocessors, or operates "stand alone"
- Differential analog voltage inputs
- Logic inputs and outputs meet both MOS and TTL voltage level specifications
- Works with 2.5V (LM336) voltage reference
- On-chip clock generator
- 0V to 5V analog input voltage range with single 5V supply
- No zero adjust required
- 0.3" standard width 20-pin DIP package
- 20-pin molded chip carrier or small outline package
- Operates ratiometrically or with 5 V_{DC}, 2.5 V_{DC}, or analog span adjusted voltage reference

Key Specifications

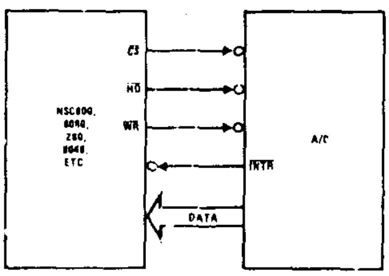
- Resolution 8 bits
- Total error ±¼ LSB, ±½ LSB and ±1 LSB
- Conversion time 100 μs

Typical Applications



TL/H/5671-1

8080 Interface



TL/H/5671-31

Error Specification (Includes Full-Scale, Zero Error, and Non-Linearity)			
Part Number	Full-Scale Adjusted	$V_{REF}/2 = 2.500\ V_{DC}$ (No Adjustments)	$V_{REF}/2$ = No Connection (No Adjustments)
ADC0801	±¼ LSB		
ADC0802		±½ LSB	
ADC0803	±½ LSB		
ADC0804		±1 LSB	
ADC0805			±1 LSB

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC}) (Note 3)	6.5V
Voltage	
Logic Control Inputs	−0.3V to +18V
At Other Input and Outputs	−0.3V to (V_{CC}+0.3V)
Lead Temp. (Soldering, 10 seconds)	
Dual-In-Line Package (plastic)	260°C
Dual-In-Line Package (ceramic)	300°C
Surface Mount Package	
Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C
Storage Temperature Range	−65°C to +150°C
Package Dissipation at T_A = 25°C	875 mW
ESD Susceptibility (Note 10)	800V

Operating Ratings (Notes 1 & 2)

Temperature Range	$T_{MIN} \le T_A \le T_{MAX}$
ADC0801/02LJ	$-55°C \le T_A \le +125°C$
ADC0801/02/03/04LCJ	$-40°C \le T_A \le +85°C$
ADC0801/02/03/05LCN	$-40°C \le T_A \le +85°C$
ADC0804LCN	$0°C \le T_A \le +70°C$
ADC0802/03/04LCV	$0°C \le T_A \le +70°C$
ADC0802/03/04LCWM	$0°C \le T_A \le +70°C$
Range of V_{CC}	4.5 V_{DC} to 6.3 V_{DC}

Electrical Characteristics

The following specifications apply for V_{CC} = 5 V_{DC}, $T_{MIN} \le T_A \le T_{MAX}$ and f_{CLK} = 640 kHz unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
ADC0801: Total Adjusted Error (Note 8)	With Full-Scale Adj. (See Section 2.5.2)			±¼	LSB
ADC0802: Total Unadjusted Error (Note 8)	$V_{REF}/2$ = 2.500 V_{DC}			±½	LSB
ADC0803: Total Adjusted Error (Note 8)	With Full-Scale Adj. (See Section 2.5.2)			±½	LSB
ADC0804: Total Unadjusted Error (Note 8)	$V_{REF}/2$ = 2.500 V_{DC}			±1	LSB
ADC0805: Total Unadjusted Error (Note 8)	$V_{REF}/2$-No Connection			±1	LSB
$V_{REF}/2$ Input Resistance (Pin 9)	ADC0801/02/03/05 ADC0804 (Note 9)	2.5 0.75	8.0 1.1		kΩ kΩ
Analog Input Voltage Range	(Note 4) V(+) or V(−)	Gnd−0.05		V_{CC}+0.05	V_{DC}
DC Common-Mode Error	Over Analog Input Voltage Range		±1/16	±⅛	LSB
Power Supply Sensitivity	V_{CC} = 5 V_{DC} ±10% Over Allowed $V_{IN}(+)$ and $V_{IN}(-)$ Voltage Range (Note 4)		±1/16	±⅛	LSB

AC Electrical Characteristics

The following specifications apply for V_{CC} = 5 V_{DC} and T_A = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
T_C	Conversion Time	f_{CLK} = 640 kHz (Note 6)	103		114	µs
T_C	Conversion Time	(Note 5, 6)	66		73	$1/f_{CLK}$
f_{CLK}	Clock Frequency Clock Duty Cycle	V_{CC} = 5V, (Note 5) (Note 5)	100 40	640	1460 60	kHz %
CR	Conversion Rate in Free-Running Mode	$\overline{INTR}$ tied to $\overline{WR}$ with $\overline{CS}$ = 0 V_{DC}, f_{CLK} = 640 kHz	8770		9708	conv/s
$t_{W(\overline{WR})L}$	Width of $\overline{WR}$ Input (Start Pulse Width)	$\overline{CS}$ = 0 V_{DC} (Note 7)	100			ns
t_{ACC}	Access Time (Delay from Falling Edge of $\overline{RD}$ to Output Data Valid)	C_L = 100 pF		135	200	ns
t_{1H}, t_{0H}	TRI-STATE Control (Delay from Rising Edge of $\overline{RD}$ to Hi-Z State)	C_L = 10 pF, R_L = 10k (See TRI-STATE Test Circuits)		125	200	ns
t_{WI}, t_{RI}	Delay from Falling Edge of $\overline{WR}$ or $\overline{RD}$ to Reset of $\overline{INTR}$			300	450	ns
C_{IN}	Input Capacitance of Logic Control Inputs			5	7.5	pF
C_{OUT}	TRI-STATE Output Capacitance (Data Buffers)			5	7.5	pF
CONTROL INPUTS [Note: CLK IN (Pin 4) is the input of a Schmitt trigger circuit and is therefore specified separately]						
V_{IN} (1)	Logical "1" Input Voltage (Except Pin 4 CLK IN)	V_{CC} = 5.25 V_{DC}	2.0		15	V_{DC}

AC Electrical Characteristics (Continued)

The following specifications apply for $V_{CC} = 5V_{DC}$ and $T_{MIN} \le T_A \le T_{MAX}$, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
CONTROL INPUTS *[Note: CLK IN (Pin 4) is the input of a Schmitt trigger circuit and is therefore specified separately]*						
V_{IN} (0)	Logical "0" Input Voltage (Except Pin 4 CLK IN)	$V_{CC} = 4.75\ V_{DC}$			0.8	V_{DC}
I_{IN} (1)	Logical "1" Input Current (All Inputs)	$V_{IN} = 5\ V_{DC}$		0.005	1	μA_{DC}
I_{IN} (0)	Logical "0" Input Current (All Inputs)	$V_{IN} = 0\ V_{DC}$	−1	−0.005		μA_{DC}
CLOCK IN AND CLOCK R						
V_T+	CLK IN (Pin 4) Positive Going Threshold Voltage		2.7	3.1	3.5	V_{DC}
V_T-	CLK IN (Pin 4) Negative Going Threshold Voltage		1.5	1.8	2.1	V_{DC}
V_H	CLK IN (Pin 4) Hysteresis $(V_T+)-(V_T-)$		0.6	1.3	2.0	V_{DC}
V_{OUT} (0)	Logical "0" CLK R Output Voltage	$I_O = 360\ \mu A$ $V_{CC} = 4.75\ V_{DC}$			0.4	V_{DC}
V_{OUT} (1)	Logical "1" CLK R Output Voltage	$I_O = -360\ \mu A$ $V_{CC} = 4.75\ V_{DC}$	2.4			V_{DC}
DATA OUTPUTS AND $\overline{INTR}$						
V_{OUT} (0)	Logical "0" Output Voltage Data Outputs $\overline{INTR}$ Output	 $I_{OUT} = 1.6\ mA$, $V_{CC} = 4.75\ V_{DC}$ $I_{OUT} = 1.0\ mA$, $V_{CC} = 4.75\ V_{DC}$			 0.4 0.4	 V_{DC} V_{DC}
V_{OUT} (1)	Logical "1" Output Voltage	$I_O = -360\ \mu A$, $V_{CC} = 4.75\ V_{DC}$	2.4			V_{DC}
V_{OUT} (1)	Logical "1" Output Voltage	$I_O = -10\ \mu A$, $V_{CC} = 4.75\ V_{DC}$	4.5			V_{DC}
I_{OUT}	TRI-STATE Disabled Output Leakage *(All Data Buffers)*	$V_{OUT} = 0\ V_{DC}$ $V_{OUT} = 5\ V_{DC}$	−3		 3	μA_{DC} μA_{DC}
I_{SOURCE}		V_{OUT} Short to Gnd, $T_A = 25°C$	4.5	6		mA_{DC}
I_{SINK}		V_{OUT} Short to V_{CC}, $T_A = 25°C$	9.0	16		mA_{DC}
POWER SUPPLY						
I_{CC}	Supply Current (Includes Ladder Current) ADC0801/02/03/04LCJ/05 ADC0804LCN/LCV/LCWM	$f_{CLK} = 640\ kHz$, $V_{REF}/2 = NC$, $T_A = 25°C$ and $\overline{CS} = 5V$		 1.1 1.9	 1.8 2.5	 mA mA

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

Note 2: All voltages are measured with respect to Gnd, unless otherwise specified. The separate A Gnd point should always be wired to the D Gnd.

Note 3: A zener diode exists, internally, from V_{CC} to Gnd and has a typical breakdown voltage of 7 V_{DC}.

Note 4: For $V_{IN}(-) \ge V_{IN}(+)$ the digital output code will be 0000 0000. Two on-chip diodes are tied to each analog input (see block diagram) which will forward conduct for analog input voltages one diode drop below ground or one diode drop greater than the V_{CC} supply. Be careful, during testing at low V_{CC} levels (4.5V), as high level analog inputs (5V) can cause this input diode to conduct—especially at elevated temperatures, and cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode. This means that as long as the analog V_{IN} does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 V_{DC} to 5 V_{DC} input voltage range will therefore require a minimum supply voltage of 4.950 V_{DC} over temperature variations, initial tolerance and loading.

Note 5: Accuracy is guaranteed at f_{CLK} = 640 kHz. At higher clock frequencies accuracy can degrade. For lower clock frequencies, the duty cycle limits can be extended so long as the minimum clock high time interval or minimum clock low time interval is no less than 275 ns.

Note 6: With an asynchronous start pulse, up to 8 clock periods may be required before the internal clock phases are proper to start the conversion process. The start request is internally latched, see *Figure 2* and section 2.0.

Note 7: The $\overline{CS}$ input is assumed to bracket the $\overline{WR}$ strobe input and therefore timing is dependent on the $\overline{WR}$ pulse width. An arbitrarily wide pulse width will hold the converter in a reset mode and the start of conversion is initiated by the low to high transition of the $\overline{WR}$ pulse (see timing diagrams).

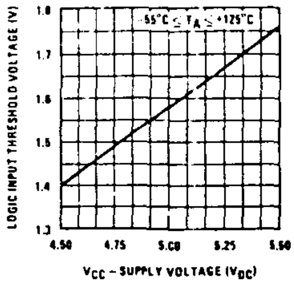
Note 8: None of these A/Ds requires a zero adjust (see section 2.5.1). To obtain zero code at other analog input voltages see section 2.5 and *Figure 5*.

Note 9: The $V_{REF}/2$ pin is the center point of a two resistor divider connected from V_{CC} to ground. Each resistor is 2.2k, except for the ADC0804LCJ where each resistor is 16k. Total ladder input resistance is the sum of the two equal resistors.

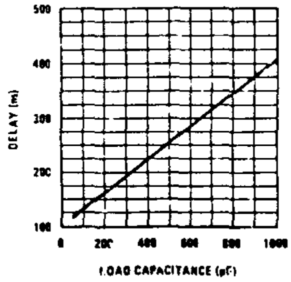
Note 10: Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Typical Performance Characteristics

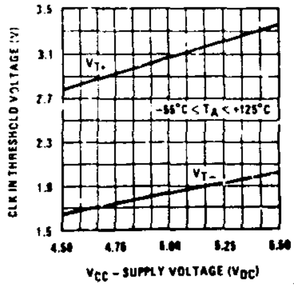
Logic Input Threshold Voltage vs. Supply Voltage



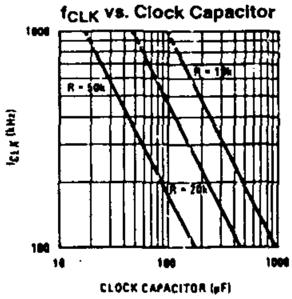
Delay From Falling Edge of $\overline{RD}$ to Output Data Valid vs. Load Capacitance



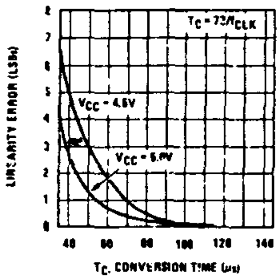
CLK IN Schmitt Trip Levels vs. Supply Voltage



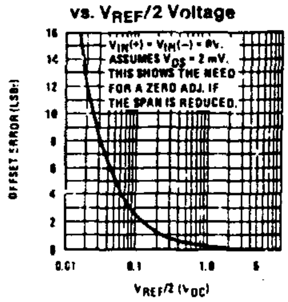
f_{CLK} vs. Clock Capacitor



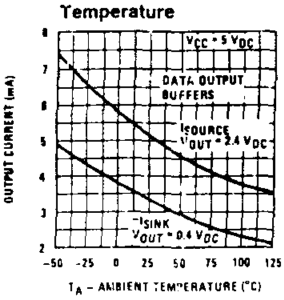
Full-Scale Error vs Conversion Time



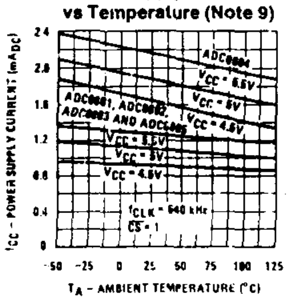
Effect of Unadjusted Offset Error vs. $V_{REF}/2$ Voltage



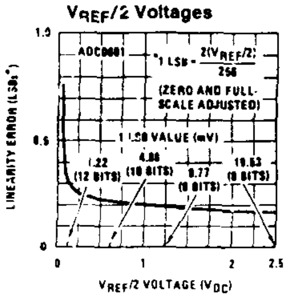
Output Current vs Temperature



Power Supply Current vs Temperature (Note 9)

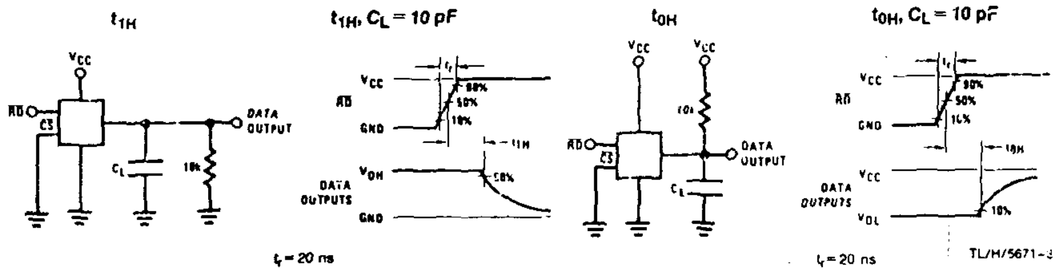


Linearity Error at Low $V_{REF}/2$ Voltages

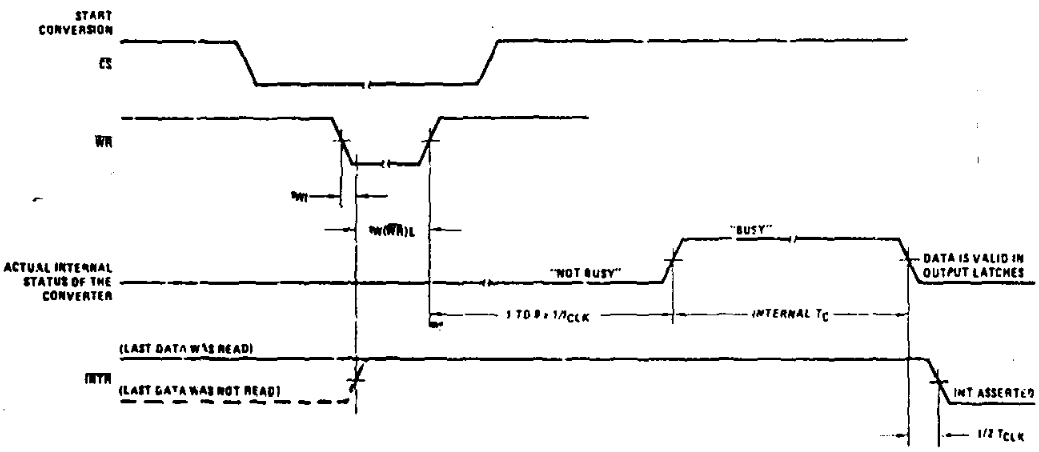


TL/H/5671-2

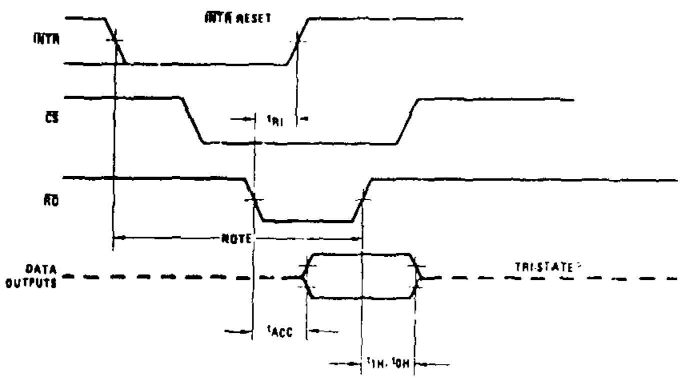
TRI-STATE Test Circuits and Waveforms



Timing Diagrams (All timing is measured from the 50% voltage points)



Output Enable and Reset $\overline{INTR}$

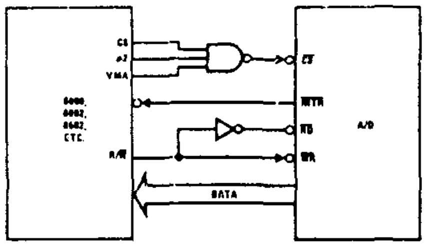


Note: Read strobe must occur 8 clock periods ($8/f_{CLK}$) after assertion of interrupt to guarantee reset of $\overline{INTR}$.

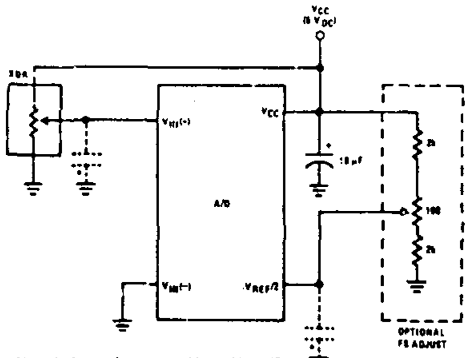
TL/H/5671-4

Typical Applications (Continued)

6800 Interface

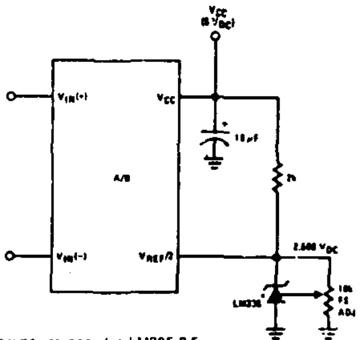


Ratiometric with Full-Scale Adjust



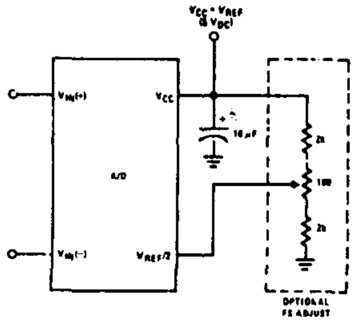
Note: before using caps at V_{IN} or $V_{REF}/2$, see section 2.3.2 Input Bypass Capacitors.

Absolute with a 2.500V Reference

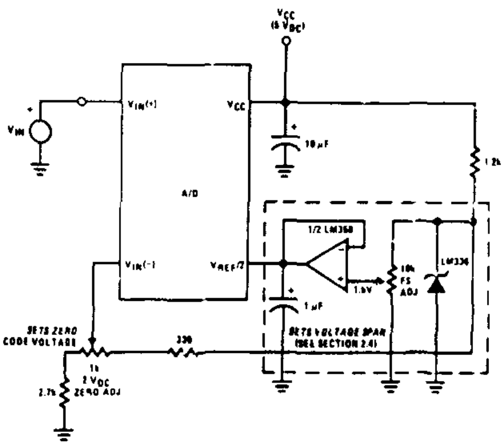


*For low power, see also LM385-2.5

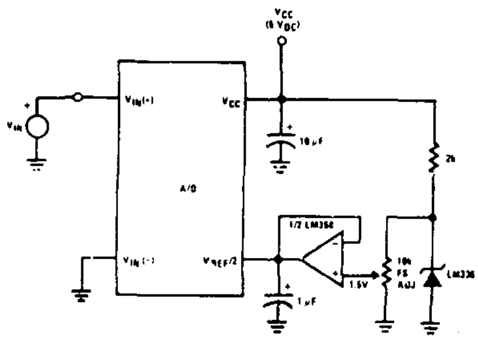
Absolute with a 5V Reference



Zero-Shift and Span Adjust: 2V ≤ V_{IN} ≤ 5V



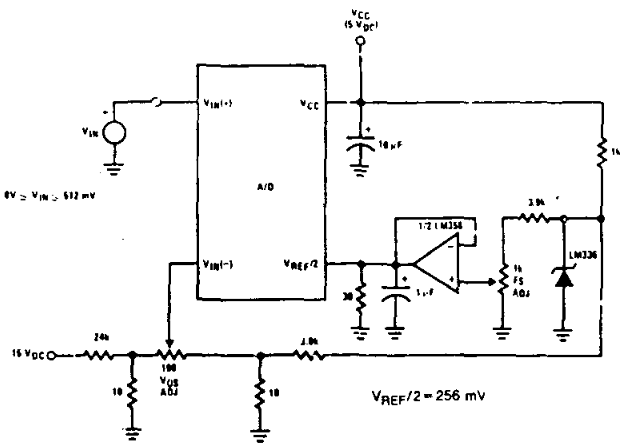
Span Adjust: 0V ≤ V_{IN} ≤ 3V



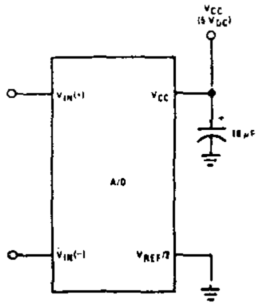
TL/H/5671–5

Typical Applications (Continued)

Directly Converting a Low-Level Signal



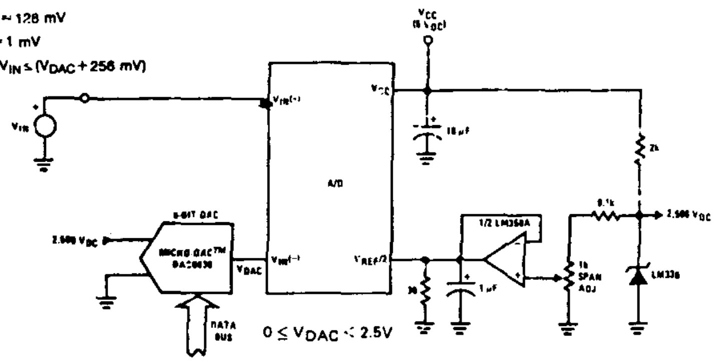
A µP Interfaced Comparator



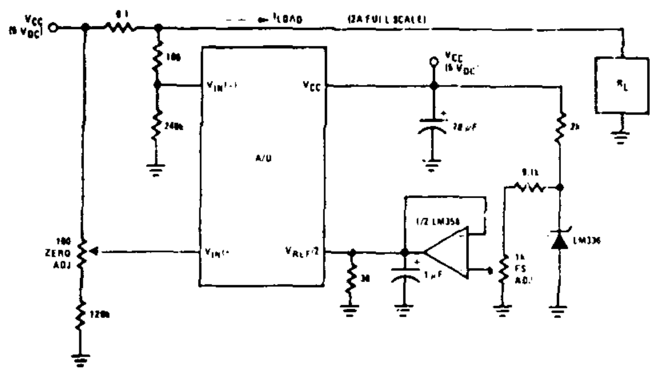
For: $V_{IN}(+) > V_{IN}(-)$
Output = FF_{HEX}
For: $V_{IN}(+) < V_{IN}(-)$
Output = 00_{HEX}

1 mV Resolution with µP Controlled Range

$V_{REF}/2 = 128$ mV
1 LSB = 1 mV
$V_{DAC} \le V_{IN} \le (V_{DAC} + 256$ mV$)$



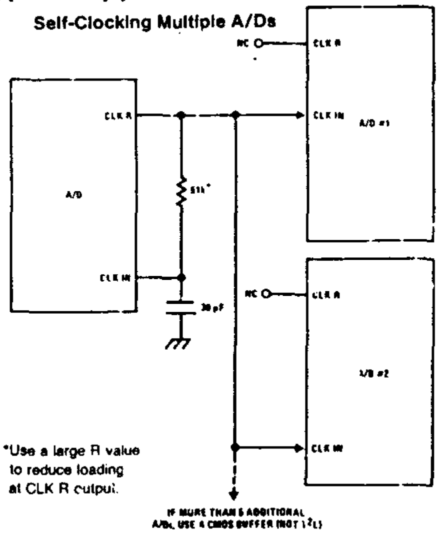
Digitizing a Current Flow



TL/H/5671–6

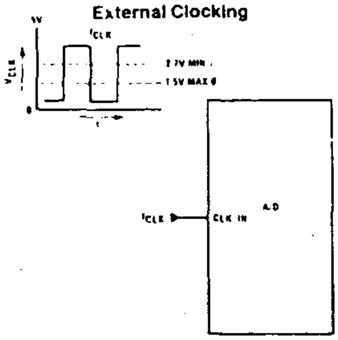
Typical Applications (Continued)

Self-Clocking Multiple A/Ds



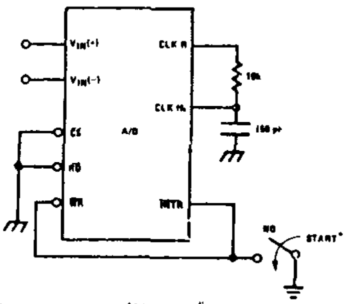
*Use a large R value to reduce loading at CLK R output.

External Clocking



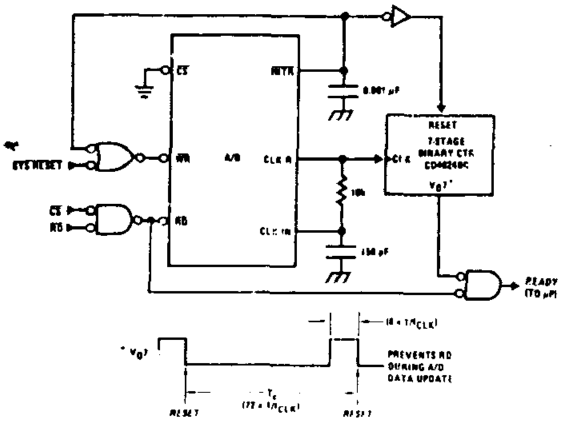
$100\ kHz \leq f_{CLK} \leq 1460\ kHz$

Self-Clocking in Free-Running Mode

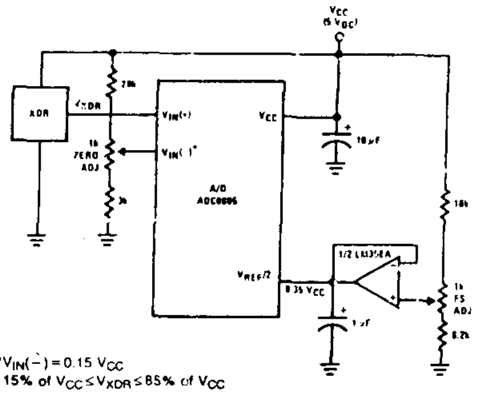


*After power-up, a momentary grounding of the $\overline{WR}$ input is needed to guarantee operation.

µP Interface for Free-Running A/D



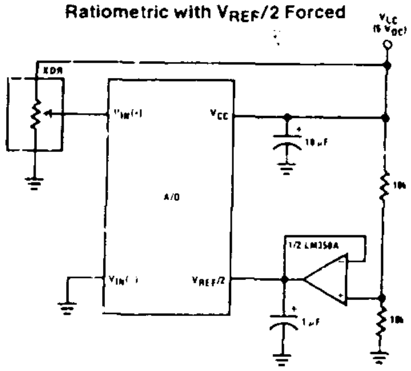
Operating with "Automotive" Ratiometric Transducers



$^*V_{IN}(-) = 0.15\ V_{CC}$

15% of $V_{CC} \leq V_{XDR} \leq 85\%$ of V_{CC}

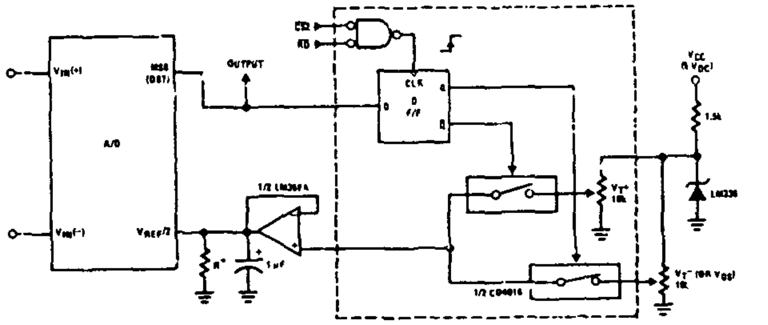
Ratiometric with $V_{REF}/2$ Forced



TL/H/5671-7

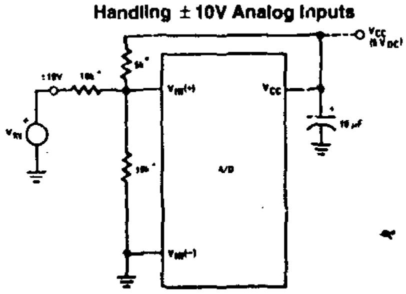
Typical Applications (Continued)

μP Compatible Differential-Input Comparator with Pre-Set V_{OS} (with or without Hysteresis)



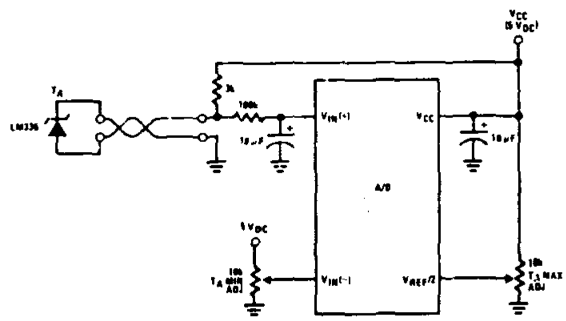
*See *Figure 5* to select R value
DB7 = "1" for $V_{IN}(+) > V_{IN}(-) + (V_{REF}/2)$
Omit circuitry within the dotted area if hysteresis is not needed

Handling ±10V Analog Inputs

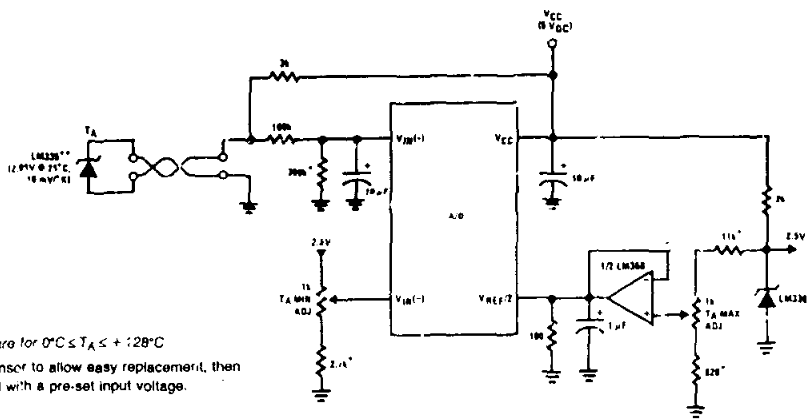


*Beckman Instruments #694-3-R10K resistor array

Low-Cost, μP Interfaced, Temperature-to-Digital Converter



μP Interfaced Temperature-to-Digital Converter



*Circuit values shown are for $0°C \le T_A \le +128°C$
**Can calibrate each sensor to allow easy replacement, then A/D can be calibrated with a pre-set input voltage.

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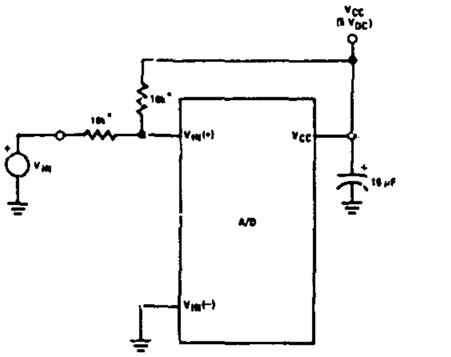
Typical Applications (Continued)

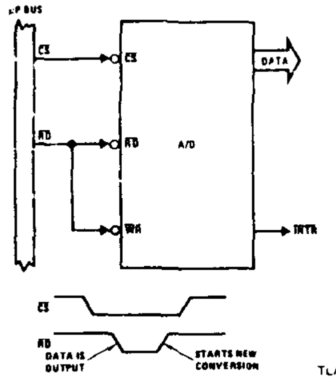
Handling ±5V Analog Inputs



TL/H/5671-33

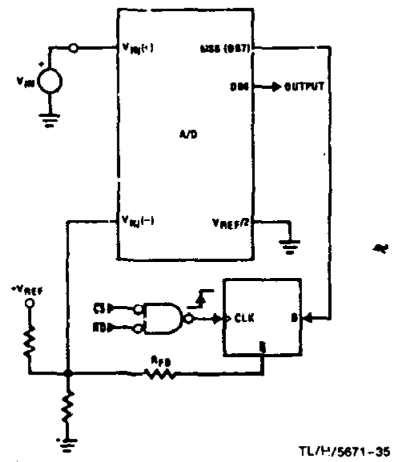
*Beckman Instruments #694-3-R10K resistor array

Read-Only Interface



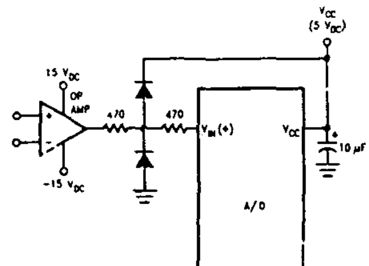
TL/H/5671-34

µP Interfaced Comparator with Hysteresis



TL/H/5671-35

Protecting the Input



Diodes are 1N914

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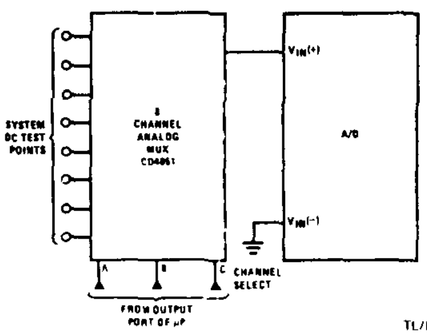
Analog Self-Test for a System



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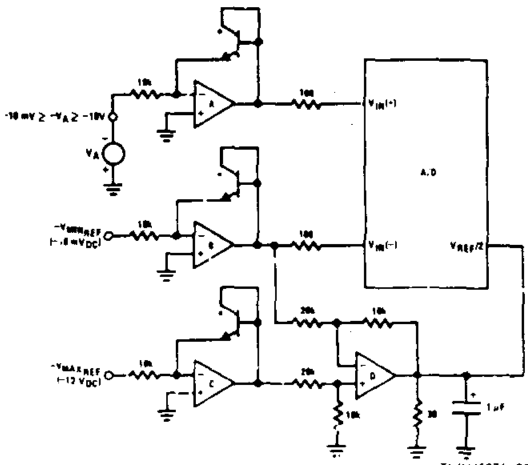
A Low-Cost, 3-Decade Logarithmic Converter



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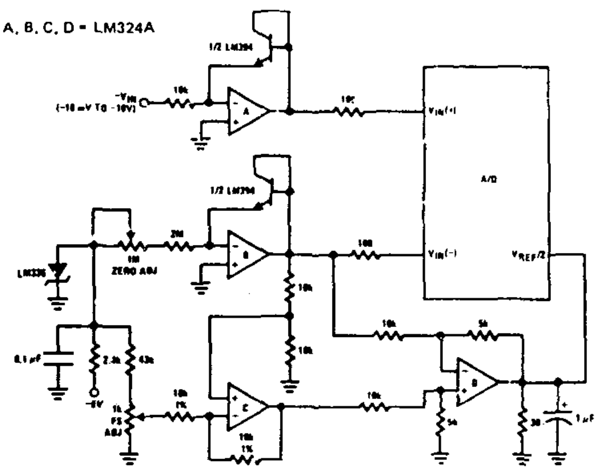
*LM389 transistors

A, B, C, D = LM324A quad op amp

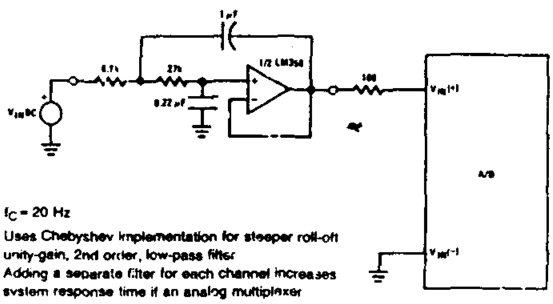
Typical Applications (Continued)

3-Decade Logarithmic A/D Converter

A, B, C, D = LM324A

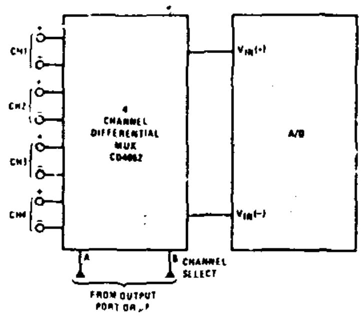


Noise Filtering the Analog Input

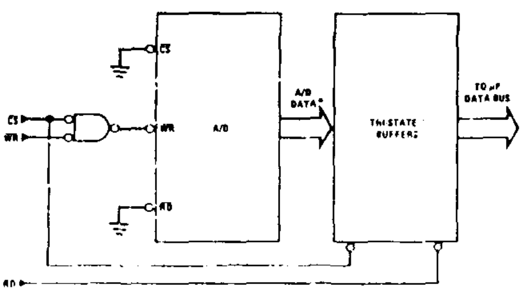


$f_C = 20$ Hz
Uses Chebyshev implementation for steeper roll-off unity-gain, 2nd order, low-pass filter
Adding a separate filter for each channel increases system response time if an analog multiplexer is used

Multiplexing Differential Inputs

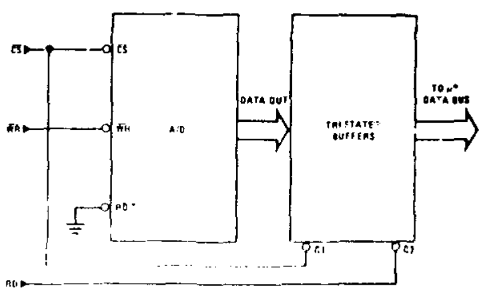


Output Buffers with A/D Data Enabled



*A/D output data is updated 1 CLK period prior to assertion of INTR

Increasing Bus Drive and/or Reducing Time on Bus



*Allows output data to set up at falling edge of CS

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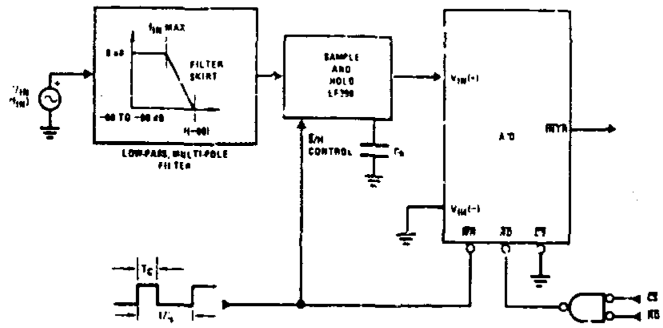
Typical Applications (Continued)

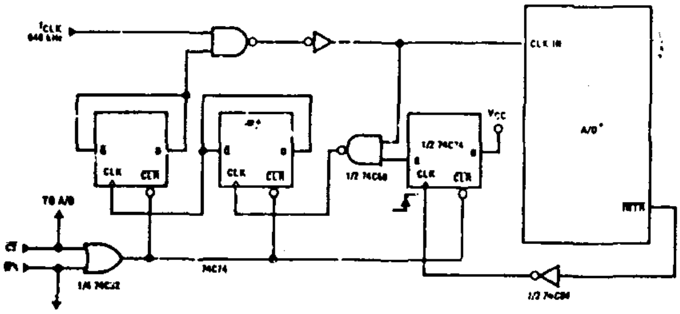
Sampling an AC Input Signal



Note 1: Oversample whenever possible [keep fs > 2f(−60)] to eliminate input frequency folding (aliasing) and to allow for the skirt response of the filter.

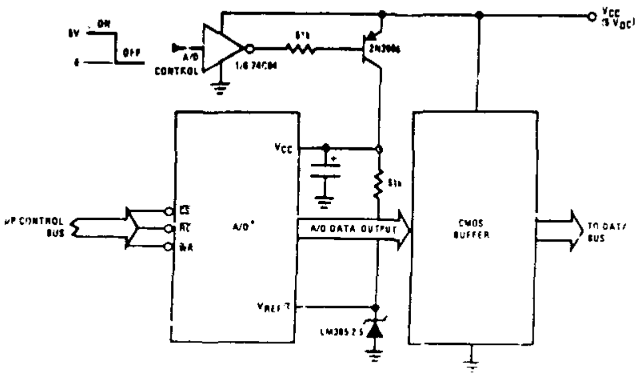
Note 2: Consider the amplitude errors which are introduced within the passband of the filter.

70% Power Savings by Clock Gating



(Complete shutdown takes ≈ 30 seconds.)

Power Savings by A/D and V_{REF} Shutdown



*Use ADC0801, 02, 03 or 05 for lowest power consumption.

Note: Logic inputs can be driven to V_{CC} with A/D supply at zero volts.

Buffer prevents data bus from overdriving output of A/D when in shutdown mode.

Functional Description

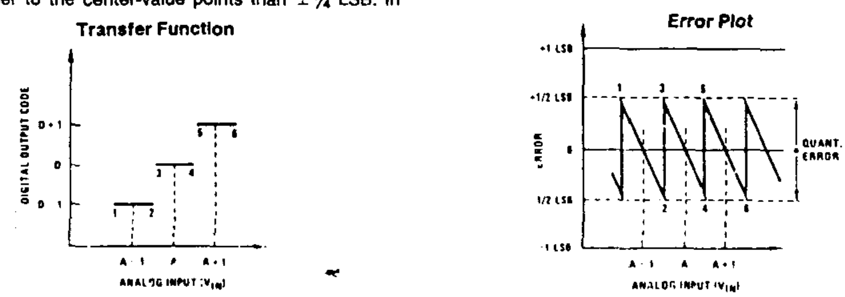
1.0 UNDERSTANDING A/D ERROR SPECS

A perfect A/D transfer characteristic (staircase waveform) is shown in *Figure 1a*. The horizontal scale is analog input voltage and the particular points labeled are in steps of 1 LSB (19.53 mV with 2.5V tied to the $V_{REF}/2$ pin). The digital output codes that correspond to these inputs are shown as D−1, D, and D+1. For the perfect A/D, not only will center-value (A−1, A, A+1, ...) analog inputs produce the correct output ditigal codes, but also each riser (the transitions between adjacent output codes) will be located ± ½ LSB *away from each center-value*. As shown, the risers are ideal and have no width. Correct digital output codes will be provided for a range of analog input voltages that extend ± ½ LSB from the ideal center-values. Each tread (the range of analog input voltage that provides the same digital output code) is therefore 1 LSB wide.

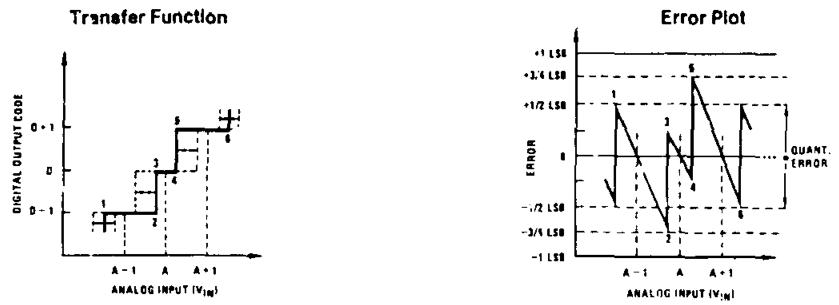
Figure 1b shows a worst case error plot for the ADC0801. All center-valued inputs are guaranteed to produce the correct output codes and the adjacent risers are guaranteed to be no closer to the center-value points than ± ¼ LSB. In other words, if we apply an analog input equal to the center-value ± ¼ LSB, *we guarantee* that the A/D will produce the correct digital code. The maximum range of the position of the code transition is indicated by the horizontal arrow and it is guaranteed to be no more than ½ LSB.

The error curve of *Figure 1c* shows a worst case error plot for the ADC0802. Here we guarantee that if we apply an analog input equal to the LSB analog voltage center-value the A/D will produce the correct digital code.

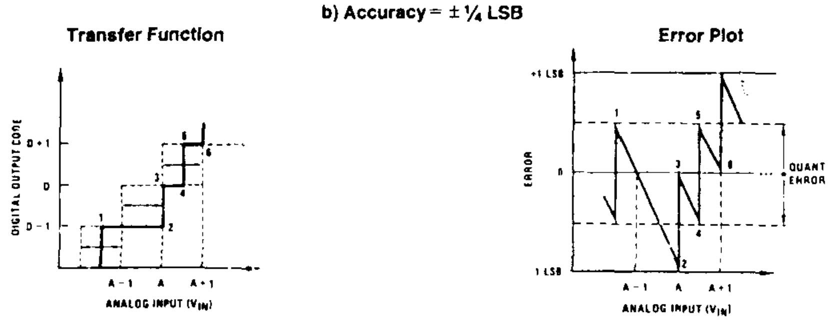
Next to each transfer function is shown the corresponding error plot. Many people may be more familiar with error plots than transfer functions. The analog input voltage to the A/D is provided by either a linear ramp or by the discrete output steps of a high resolution DAC. Notice that the error is continuously displayed and includes the quantization uncertainty of the A/D. For example the error at point 1 of *Figure 1a* is + ½ LSB because the digital code appeared ½ LSB in advance of the center-value of the tread. The error plots always have a constant negative slope and the abrupt upside steps are always 1 LSB in magnitude.



a) Accuracy = ±0 LSB: A Perfect A/D



b) Accuracy = ± ¼ LSB



c) Accuracy = ± ½ LSB

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FIGURE 1. Clarifying the Error Specs of an A/D Converter

Functional Description (Continued)

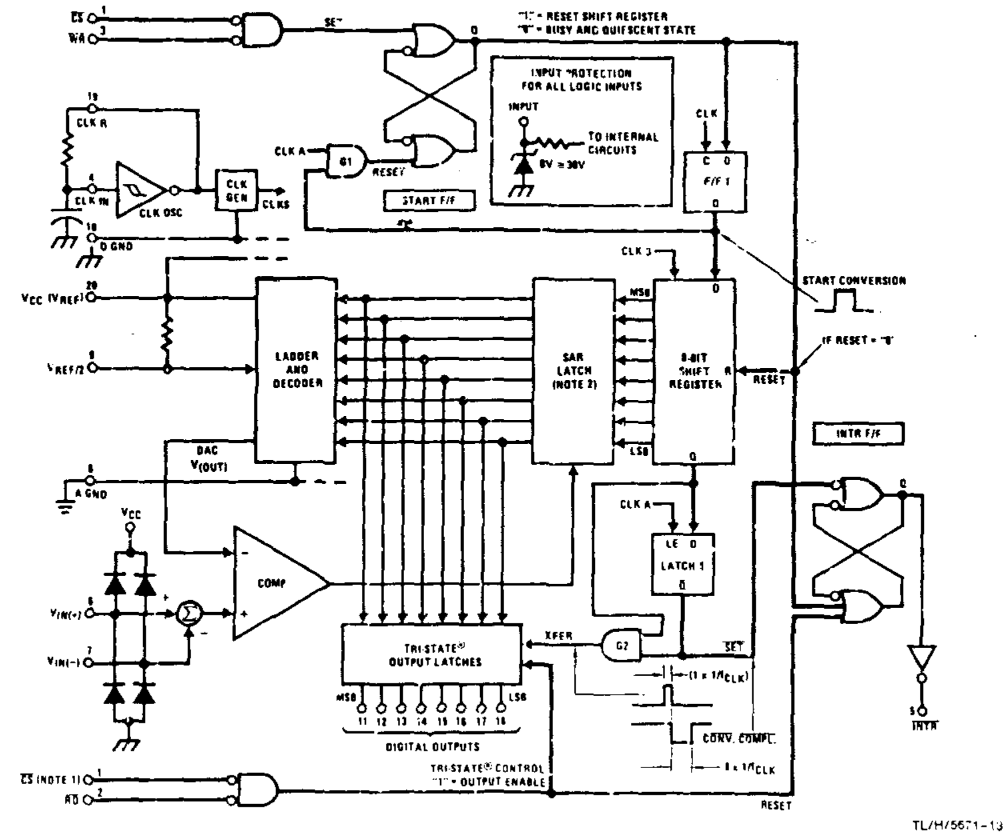
2.0 FUNCTIONAL DESCRIPTION

The ADC0801 series contains a circuit equivalent of the 256R network. Analog switches are sequenced by successive approximation logic to match the analog difference input voltage [$V_{IN}(+) - V_{IN}(-)$] to a corresponding tap on the R network. The most significant bit is tested first and after 8 comparisons (64 clock cycles) a digital 8-bit binary code (1111 1111 = full-scale) is transferred to an output latch and then an interrupt is asserted ($\overline{INTR}$ makes a high-to-low transition). A conversion in process can be *interrupted* by issuing a second start command. The device may be operated in the free-running mode by connecting $\overline{INTR}$ to the $\overline{WR}$ input with $\overline{CS}=0$. To ensure start-up under all possible conditions, an external $\overline{WR}$ pulse is required during the first power-up cycle.

On the high-to-low transition of the $\overline{WR}$ input the internal SAR latches and the shift register stages are reset. As long as the $\overline{CS}$ input and $\overline{WR}$ input remain low, the A/D will remain in a reset state. ***Conversion will start from 1 to 8 clock periods after at least one of these inputs makes a low-to-high transition.***

A functional diagram of the A/D converter is shown in *Figure 2*. All of the package pinouts are shown and the major logic control paths are drawn in heavier weight lines.

The converter is started by having $\overline{CS}$ and $\overline{WR}$ simultaneously low. This sets the start flip-flop (F/F) and the resulting "1" level resets the 8-bit shift register, resets the Interrupt (INTR) F/F and inputs a "1" to the D flop, F/F1, which is at the input end of the 8-bit shift register. Internal clock signals then transfer this "1" to the Q output of F/F1. The AND gate, G1, combines this "1" output with a clock signal to provide a reset signal to the start F/F. If the set signal is no longer present (either $\overline{WR}$ or $\overline{CS}$ is a "1") the start F/F is reset and the 8-bit shift register then can have the "1" clocked in, which starts the conversion process. If the set signal were to still be present, this reset pulse would have no effect (both outputs of the start F/F would momentarily be at a "1" level) and the 8-bit shift register would continue to be held in the reset mode. This logic therefore allows for wide $\overline{CS}$ and $\overline{WR}$ signals and the converter will start after at least one of these signals returns high and the internal clocks again provide a reset signal for the start F/F.



Note 1: $\overline{CS}$ shown twice for clarity.

Note 2: SAR = Successive Approximation Register.

FIGURE 2. Block Diagram

Functional Description (Continued)

After the "1" is clocked through the 8-bit shift register (which completes the SAR search) it appears as the input to the D-type latch, LATCH 1. As soon as this "1" is output from the shift register, the AND gate, G2, causes the new digital word to transfer to the TRI-STATE output latches. When LATCH 1 is subsequently enabled, the Q output makes a high-to-low transition which causes the INTR F/F to set. An inverting buffer then supplies the $\overline{INTR}$ input signal.

Note that this $\overline{SET}$ control of the INTR F/F remains low for 8 of the external clock periods (as the internal clocks run at ⅛ of the frequency of the external clock). If the data output is continuously enabled ($\overline{CS}$ and $\overline{RD}$ both held low), the $\overline{INTR}$ output will still signal the end of conversion (by a high-to-low transition), because the $\overline{SET}$ input can control the Q output of the INTR F/F even though the RESET input is constantly at a "1" level in this operating mode. This $\overline{INTR}$ output will therefore stay low for the duration of the $\overline{SET}$ signal, which is 8 periods of the external clock frequency (assuming the A/D is not started during this interval).

When operating in the free-running or continuous conversion mode ($\overline{INTR}$ pin tied to $\overline{WR}$ and $\overline{CS}$ wired low—see also section 2.8), the START F/F is SET by the high-to-low transition of the $\overline{INTR}$ signal. This resets the SHIFT REGISTER which causes the input to the D-type latch, LATCH 1, to go low. As the latch enable input is still present, the $\overline{Q}$ output will go high, which then allows the INTR F/F to be RESET. This reduces the width of the resulting $\overline{INTR}$ output pulse to only a few propagation delays (approximately 300 ns).

When data is to be read, the combination of both $\overline{CS}$ and $\overline{RD}$ being low will cause the INTR F/F to be reset and the TRI-STATE output latches will be enabled to provide the 8-bit digital outputs.

2.1 Digital Control Inputs

The digital control inputs ($\overline{CS}$, $\overline{RD}$, and $\overline{WR}$) meet standard T²L logic voltage levels. These signals have been renamed when compared to the standard A/D Start and Output Enable labels. In addition, these inputs are active low to allow an easy interface to microprocessor control busses. For non-microprocessor based applications, the $\overline{CS}$ input (pin 1) can be grounded and the standard A/D Start function is obtained by an active low pulse applied at the $\overline{WR}$ input (pin 3) and the Output Enable function is caused by an active low pulse at the $\overline{RD}$ input (pin 2).

2.2 Analog Differential Voltage Inputs and Common-Mode Rejection

This A/D has additional applications flexibility due to the analog differential voltage input. The $V_{IN}(-)$ input (pin 7) can be used to automatically subtract a fixed voltage value from the input reading (tare correction). This is also useful in 4 mA–20 mA current loop conversion. In addition, common-mode noise can be reduced by use of the differential input.

The time interval between sampling $V_{IN}(+)$ and $V_{IN}(-)$ is 4-½ clock periods. The maximum error voltage due to this slight time difference between the input voltage samples is given by:

$$\Delta V_e(MAX) = (V_P)(2\pi f_{cm})\left(\frac{4.5}{f_{CLK}}\right),$$

where:

ΔV_e is the error voltage due to sampling delay

V_P is the peak value of the common-mode voltage

f_{cm} is the common-mode frequency

As an example, to keep this error to ¼ LSB (~5 mV) when operating with a 60 Hz common-mode frequency, f_{cm}, and using a 640 kHz A/D clock, f_{CLK}, would allow a peak value of the common-mode voltage, V_P, which is given by:

$$V_P = \frac{[\Delta V_{e(MAX)}(f_{CLK})]}{(2\pi f_{cm})(4.5)}$$

or

$$V_P = \frac{(5 \times 10^{-3})(640 \times 10^3)}{(6.28)(60)(4.5)}$$

which gives

$V_P \cong 1.9V.$

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

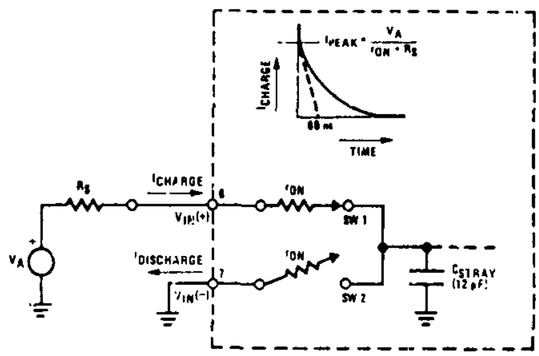
An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).

2.3 Analog Inputs

2.3.1 Input Current

Normal Mode

Due to the internal switching action, displacement currents will flow at the analog inputs. This is due to on-chip stray capacitance to ground as shown in *Figure 3*.



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r_{ON} of SW 1 and SW 2 ≅ 5 kΩ

$\tau = r_{ON} C_{STRAY}$ ≅ 5 kΩ × 12 pF = 60 ns

FIGURE 3. Analog Input Impedance

Functional Description (Continued)

The voltage on this capacitance is switched and will result in currents entering the $V_{IN}(+)$ input pin and leaving the $V_{IN}(-)$ input which will depend on the analog differential input voltage levels. These current transients occur at the leading edge of the internal clocks. *They rapidly decay and do not cause errors* as the on-chip comparator is strobed at the end of the clock period.

Fault Mode

If the voltage source applied to the $V_{IN}(+)$ or $V_{IN}(-)$ pin exceeds the allowed operating range of $V_{CC}+50$ mV, large *input currents can flow through a parasitic diode to the V_{CC} pin.* If these currents can exceed the 1 mA max allowed spec, an external diode (1N914) should be added to bypass this current to the V_{CC} pin (with the current bypassed with this diode, the voltage at the $V_{IN}(+)$ pin can exceed the V_{CC} voltage by the forward voltage of this diode).

2.3.2 Input Bypass Capacitors

Bypass capacitors at the inputs will average these charges and cause a DC current to flow through the output resistances of the analog signal sources. This charge pumping action is worse for continuous conversions with the $V_{IN}(+)$ input voltage at full-scale. For continuous conversions with a 640 kHz clock frequency with the $V_{IN}(+)$ input at 5V, this DC current is at a maximum of approximately 5 μA. Therefore, *bypass capacitors should not be used at the analog inputs or the $V_{REF}/2$ pin* for high resistance sources (> 1 kΩ). If input bypass capacitors are necessary for noise filtering and high source resistance is desirable to minimize capacitor size, the detrimental effects of the voltage drop across this input resistance, which is due to the average value of the input current, can be *eliminated with a full-scale adjustment* while the given source resistor and input bypass capacitor are both in place. This is possible because the average value of the input current is a precise linear function of the differential input voltage.

2.3.3 Input Source Resistance

Large values of source resistance where an input bypass capacitor is not used, *will not cause errors* as the input currents settle out prior to the comparison time. If a low pass filter is required in the system, use a low valued series resistor (≤ 1 kΩ) for a passive RC section or add an op amp RC active low pass filter. For low source resistance applications, (≤ 1 kΩ), a 0.1 μF bypass capacitor at the inputs will *prevent noise pickup due to series lead inductance* of a long wire. A 100Ω series resistor can be used to isolate this capacitor—both the R and C are placed outside the feedback loop—from the output of an op amp, if used.

2.3.4 Noise

The leads to the analog inputs (pin 6 and 7) should be kept *as short as possible to minimize input noise coupling.* Both noise and undesired digital clock coupling to these inputs can cause system errors. The source resistance for these inputs should, in general, be kept below 5 kΩ. Larger values of source resistance can cause undesired system noise pickup. Input bypass capacitors, placed from the analog inputs to ground, will eliminate system noise pickup but can create analog scale errors *as these capacitors will average* the transient input switching currents of the A/D (see section 2.3.1.). This scale error depends on both a large source resistance and the use of an input bypass capacitor. This error can be eliminated by doing a full-scale adjustment of the A/D (adjust $V_{REF}/2$ for a proper full-scale reading—see section 2.5.2 on Full-Scale Adjustment) *with the source resistance and input bypass capacitor in place.*

2.4 Reference Voltage

2.4.1 Span Adjust

For maximum applications flexibility, these A/Ds have been designed to accommodate a 5 V_{DC}, 2.5 V_{DC} or an adjusted voltage reference. This has been achieved in the design of the IC as shown in *Figure 4.*

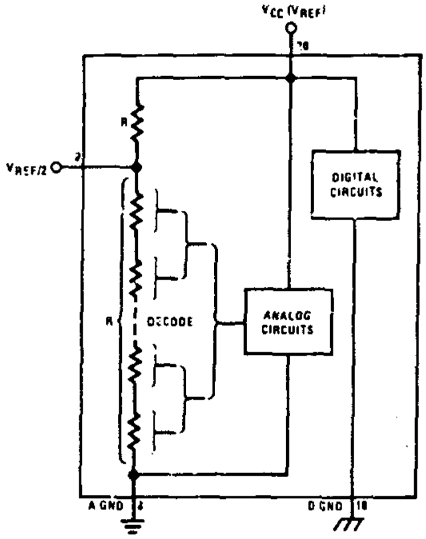

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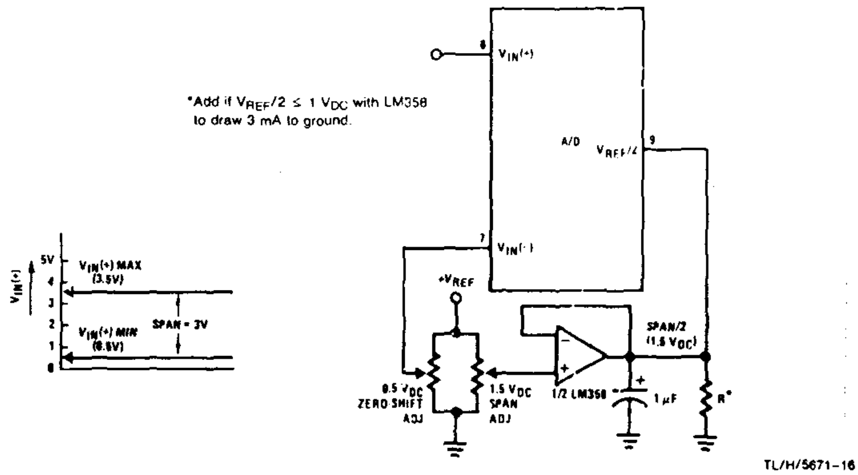
FIGURE 4. The $V_{REFERENCE}$ Design on the IC

Notice that the reference voltage for the IC is either ½ of *the voltage applied to the V_{CC} supply pin, or is equal to the* voltage that is externally forced at the $V_{REF}/2$ pin. This allows for a ratiometric voltage reference using the V_{CC} supply, a 5 V_{DC} reference voltage can be used for the V_{CC} supply or a voltage less than 2.5 V_{DC} can be applied to the $V_{REF}/2$ input for increased application flexibility. The internal gain to the $V_{REF}/2$ input is 2, making the full-scale differential input voltage *twice the voltage at pin 9.*

An example of the use of an adjusted reference voltage is to accommodate a reduced span—*or dynamic voltage range* of the analog input voltage. If the analog input voltage were *to range* from 0.5 V_{DC} to 3.5 V_{DC}, instead of 0V to 5 V_{DC}, the span would be 3V as shown in *Figure 5.* With 0.5 V_{DC} applied to the $V_{IN}(-)$ pin to absorb the offset, the reference voltage can be made equal to ½ of the 3V span or 1.5 V_{DC}. The A/D now will encode the $V_{IN}(+)$ signal from 0.5V to 3.5 V with the 0.5V input corresponding to zero and the 3.5 V_{DC} input corresponding to full-scale. The full 8 bits of resolution *are therefore applied over this reduced analog input voltage* range.

3

Functional Description (Continued)



a) Analog Input Signal Example

b) Accommodating an Analog Input from 0.5V (Digital Out = 00_{HEX}) to 3.5V (Digital Out = FF_{HEX})

FIGURE 5. Adapting the A/D Analog Input Voltages to Match an Arbitrary Input Signal Range

2.4.2 Reference Accuracy Requirements

The converter can be operated in a ratiometric mode or an absolute mode. In ratiometric converter applications, the magnitude of the reference voltage is a factor in both the output of the source transducer and the output of the A/D converter and therefore cancels out in the final digital output code. The ADC0805 is specified particularly for use in ratiometric applications with no adjustments required. In absolute conversion applications, both the initial value and the temperature stability of the reference voltage are important factors in the accuracy of the A/D converter. For $V_{REF}/2$ voltages of 2.4 V_{DC} nominal value, initial errors of ±10 mV_{DC} will cause conversion errors of ±1 LSB due to the gain of 2 of the $V_{REF}/2$ input. In reduced span applications, the initial value and the stability of the $V_{REF}/2$ input voltage become even more important. For example, if the span is reduced to 2.5V, the analog input LSB voltage value is correspondingly reduced from 20 mV (5V span) to 10 mV and 1 LSB at the $V_{REF}/2$ input becomes 5 mV. As can be seen, this reduces the allowed initial tolerance of the reference voltage and requires correspondingly less absolute change with temperature variations. Note that spans smaller than 2.5V place even tighter requirements on the initial accuracy and stability of the reference source.

In general, the magnitude of the reference voltage will require an initial adjustment. Errors due to an improper value of reference voltage appear as full-scale errors in the A/D transfer function. IC voltage regulators may be used for references if the ambient temperature changes are not excessive. The LM336B 2.5V IC reference diode (from National Semiconductor) has a temperature stability of 1.8 mV typ (6 mV max) over $0°C \leq T_A \leq +70°C$. Other temperature range parts are also available.

2.5 Errors and Reference Voltage Adjustments

2.5.1 Zero Error

The zero of the A/D does not require adjustment. If the minimum analog input voltage value, $V_{IN(MIN)}$, is not ground, a zero offset can be done. The converter can be made to output 0000 0000 digital code for this minimum input voltage by biasing the A/D $V_{IN}(-)$ input at this $V_{IN(MIN)}$ value (see Applications section). This utilizes the differential mode operation of the A/D.

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the V_{IN} (−) input and applying a small magnitude positive voltage to the V_{IN} (+) input. Zero error is the difference between the actual DC input voltage that is necessary to just cause an output digital code transition from 0000 0000 to 0000 0001 and the ideal ½ LSB value (½ LSB = 9.8 mV for $V_{REF}/2 = 2.500\ V_{DC}$).

2.5.2 Full-Scale

The full-scale adjustment can be made by applying a differential input voltage that is 1½ LSB less than the desired analog full-scale voltage range and then adjusting the magnitude of the $V_{REF}/2$ input (pin 9 or the V_{CC} supply if pin 9 is not used) for a digital output code that is just changing from 1111 1110 to 1111 1111.

Functional Description (Continued)

2.5.3 Adjusting for an Arbitrary Analog Input Voltage Range

If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal that *does not go to ground*) this new zero reference should be properly adjusted first. A $V_{IN}(+)$ voltage that equals this desired zero reference plus ½ LSB (where the LSB is calculated for the desired analog span, 1 LSB = analog span/256) is applied to pin 6 and the zero reference voltage at pin 7 should then be adjusted to just obtain the 00_{HEX} to 01_{HEX} code transition.

The full-scale adjustment should then be made (with the proper $V_{IN}(-)$ voltage applied) by forcing a voltage to the $V_{IN}(+)$ input which is given by:

$$V_{IN}(+)\ fs\ adj = V_{MAX} - 1.5\left[\frac{(V_{MAX} - V_{MIN})}{256}\right],$$

where:

V_{MAX} = The high end of the analog input range

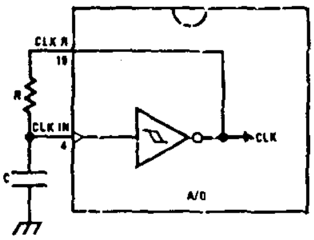
and

V_{MIN} = the low end (the offset zero) of the analog range. (Both are ground referenced.)

The $V_{REF}/2$ (or V_{CC}) voltage is then adjusted to provide a code change from FE_{HEX} to FF_{HEX}. This completes the adjustment procedure.

2.6 Clocking Option

The clock for the A/D can be derived from the CPU clock or an external RC can be added to provide self-clocking. The CLK IN (pin 4) makes use of a Schmitt trigger as shown in *Figure 6*.



$$f_{CLK} \cong \frac{1}{1.1\ RC}$$

$R \cong 10\ k\Omega$

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FIGURE 6. Self-Clocking the A/D

Heavy capacitive or DC loading of the clock R pin should be avoided as this will disturb normal converter operation. Loads less than 50 pF, such as driving up to 7 A/D converter clock inputs from a single clock R pin of 1 converter, are allowed. For larger clock line loading, a CMOS or low power TTL buffer or PNP input logic should be used to minimize the loading on the clock R pin (do not use a standard TTL buffer).

2.7 Restart During a Conversion

If the A/D is restarted ($\overline{CS}$ and $\overline{WR}$ go low and return high) during a conversion, the converter is reset and a new conversion is started. The output data latch is not updated if the conversion in process is not allowed to be completed, therefore the data of the previous conversion remains in this latch. The $\overline{INTR}$ output simply remains at the "1" level.

2.8 Continuous Conversions

For operation in the free-running mode an initializing pulse should be used, following power-up, to ensure circuit operation. In this application, the $\overline{CS}$ input is grounded and the $\overline{WR}$ input is tied to the $\overline{INTR}$ output. This $\overline{WR}$ and $\overline{INTR}$ node should be momentarily forced to logic low following a power-up cycle to guarantee operation.

2.9 Driving the Data Bus

This MOS A/D, like MOS microprocessors and memories, will require a bus driver when the total capacitance of the data bus gets large. Other circuitry, which is tied to the data bus, will add to the total capacitive loading, even in TRI-STATE (high impedance mode). Backplane bussing also greatly adds to the stray capacitance of the data bus.

There are some alternatives available to the designer to handle this problem. Basically, the capacitive loading of the data bus slows down the response time, even though DC specifications are still met. For systems operating with a relatively slow CPU clock frequency, more time is available in which to establish proper logic levels on the bus and therefore higher capacitive loads can be driven (see typical characteristics curves).

At higher CPU clock frequencies time can be extended for I/O reads (and/or writes) by inserting wait states (8080) or using clock extending circuits (6800).

Finally, if time is short and capacitive loading is high, external bus drivers must be used. These can be TRI-STATE buffers (low power Schottky such as the DM74LS240 series is recommended) or special higher drive current products which are designed as bus drivers. High current bipolar bus drivers with PNP inputs are recommended.

2.10 Power Supplies

Noise spikes on the V_{CC} supply line can cause conversion errors as the comparator will respond to this noise. A low inductance tantalum filter capacitor should be used close to the converter V_{CC} pin and values of 1 µF or greater are recommended. If an unregulated voltage is available in the system, a separate LM340LAZ-5.0, TO-92, 5V voltage regulator for the converter (and other analog circuitry) will greatly reduce digital noise on the V_{CC} supply.

2.11 Wiring and Hook-Up Precautions

Standard digital wire wrap sockets are not satisfactory for breadboarding this A/D converter. Sockets on PC boards can be used and all logic signal wires and leads should be grouped and kept as far away as possible from the analog signal leads. Exposed leads to the analog inputs can cause undesired digital noise and hum pickup, therefore shielded leads may be necessary in many applications.

Functional Description (Continued)

A single point analog ground that is separate from the logic ground points should be used. The power supply bypass capacitor and the self-clocking capacitor (if used) should both be returned to digital ground. Any $V_{REF}/2$ bypass capacitors, analog input filter capacitors, or input signal shielding should be returned to the analog ground point. A test for proper grounding is to measure the zero error of the A/D converter. Zero errors in excess of ¼ LSB can usually be traced to improper board layout and wiring (see section 2.5.1 for measuring the zero error).

3.0 TESTING THE A/D CONVERTER

There are many degrees of complexity associated with testing an A/D converter. One of the simplest tests is to apply a known analog input voltage to the converter and use LEDs to display the resulting digital output code as shown in *Figure 7*.

For ease of testing, the $V_{REF}/2$ (pin 9) should be supplied with 2.560 V_{DC} and a V_{CC} supply voltage of 5.12 V_{DC} should be used. This provides an LSB value of 20 mV.

If a full-scale adjustment is to be made, an analog input voltage of 5.090 V_{DC} (5.120–1½ LSB) should be applied to the $V_{IN}(+)$ pin with the $V_{IN}(-)$ pin grounded. The value of the $V_{REF}/2$ input voltage should then be adjusted until the digital output code is just changing from 1111 1110 to 1111 1111. This value of $V_{REF}/2$ should then be used for all the tests.

The digital output LED display can be decoded by dividing the 8 bits into 2 hex characters, the 4 most significant (MS) and the 4 least significant (LS). Table I shows the fractional binary equivalent of these two 4-bit groups. By adding the voltages obtained from the "VMS" and "VLS" columns in Table I, the nominal value of the digital display (when $V_{REF}/2$ = 2.560V) can be determined. For example, for an output LED display of 1011 0110 or B6 (in hex), the voltage values from the table are 3.520 + 0.120 or 3.640 V_{DC}. These voltage values represent the center-values of a perfect A/D converter. The effects of quantization error have to be accounted for in the interpretation of the test results.

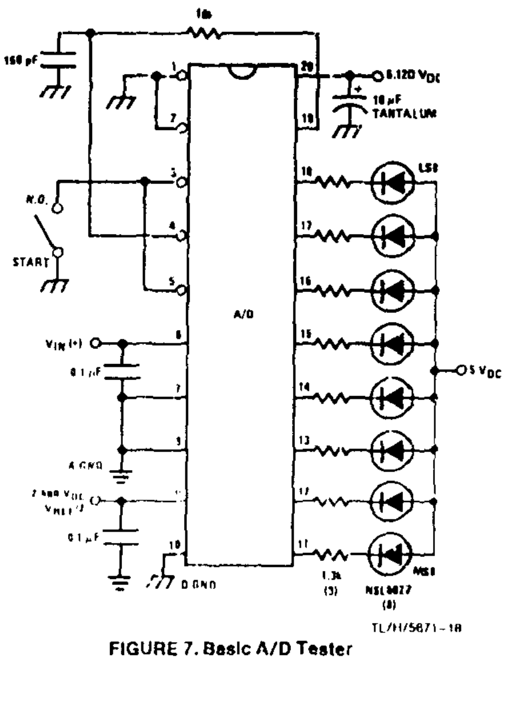

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FIGURE 7. Basic A/D Tester

For a higher speed test system, or to obtain plotted data, a digital-to-analog converter is needed for the test set-up. An accurate 10-bit DAC can serve as the precision voltage source for the A/D. Errors of the A/D under test can be expressed as either analog voltages or differences in 2 digital words.

A basic A/D tester that uses a DAC and provides the error as an analog output voltage is shown in *Figure 8*. The 2 op amps can be eliminated if a lab DVM with a numerical subtraction feature is available to read the difference voltage, "A–C", directly. The analog input voltage can be supplied by a low frequency ramp generator and an X-Y plotter can be used to provide analog error (Y axis) versus analog input (X axis). The construction details of a tester of this type are provided in the NSC application note AN-179, "Analog-to-Digital Converter Testing".

For operation with a microprocessor or a computer-based test system, it is more convenient to present the errors digitally. This can be done with the circuit of *Figure 9*, where the output code transitions can be detected as the 10-bit DAC is incremented. This provides ¼ LSB steps for the 8-bit A/D under test. If the results of this test are automatically plotted with the analog input on the X axis and the error (in LSB's) as the Y axis, a useful transfer function of the A/D under test results. For acceptance testing, the plot is not necessary and the testing speed can be increased by establishing internal limits on the allowed error for each code.

4.0 MICROPROCESSOR INTERFACING

To dicuss the interface with 8080A and 6800 microprocessors, a common sample subroutine structure is used. The microprocessor starts the A/D, reads and stores the results of 16 successive conversions, then returns to the user's program. The 16 data bytes are stored in 16 successive memory locations. All Data and Addresses will be given in hexadecimal form. Software and hardware details are provided separately for each type of microprocessor.

4.1 Interfacing 8080 Microprocessor Derivatives (8048, 8085)

This converter has been designed to directly interface with derivatives of the 8080 microprocessor. The A/D can be mapped into memory space (using standard memory address decoding for $\overline{CS}$ and the $\overline{MEMR}$ and $\overline{MEMW}$ strobes) or it can be controlled as an I/O device by using the $\overline{I/O\ R}$ and $\overline{I/O\ W}$ strobes and decoding the address bits A0 → A7 (or address bits A8 → A15 as they will contain the same 8-bit address information) to obtain the $\overline{CS}$ input. Using the I/O space provides 256 additional addresses and may allow a simpler 8-bit address decoder but the data can only be input to the accumulator. To make use of the additional memory reference instructions, the A/D should be mapped into memory space. An example of an A/D in I/O space is shown in *Figure 10*.

Functional Description (Continued)

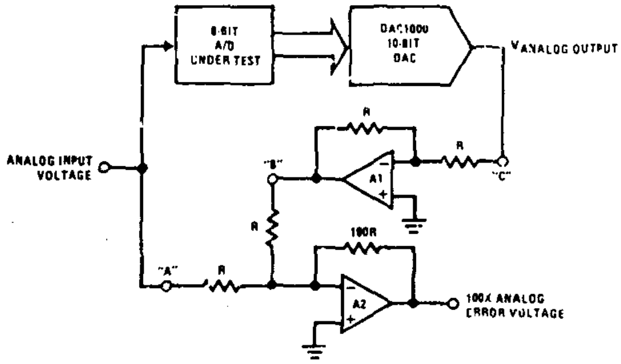

FIGURE 8. A/D Tester with Analog Error Output

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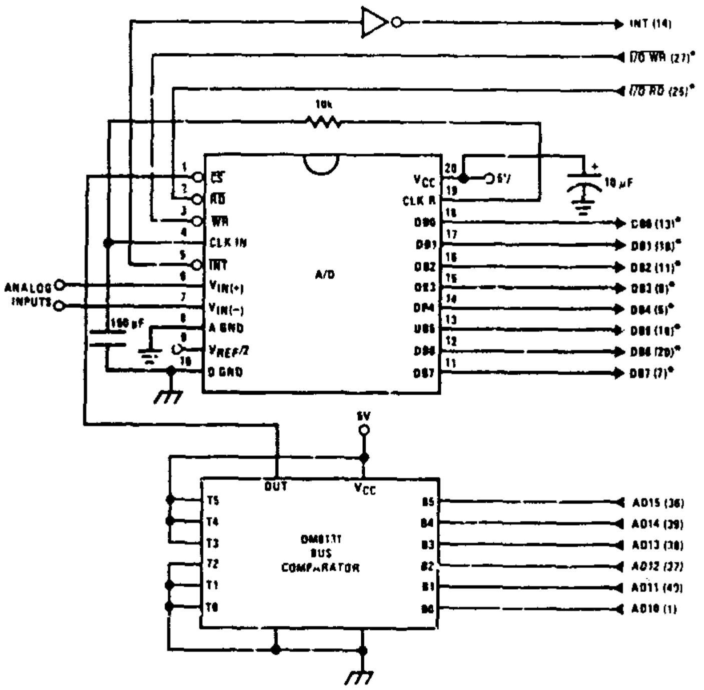
FIGURE 9. Basic "Digital" A/D Tester

TABLE I. DECODING THE DIGITAL OUTPUT LEDs

HEX	BINARY				FRACTIONAL BINARY VALUE FOR		OUTPUT VOLTAGE CENTER VALUES WITH $V_{REF}/2 = 2.560\ V_{DC}$	
					MS GROUP	LS GROUP	VMS GROUP*	VLS GROUP*
F	1	1	1	1	15/16	15/256	4.800	0.300
E	1	1	1	0	7/8	7/128	4.480	0.280
D	1	1	0	1	13/16	13/256	4.160	0.260
C	1	1	0	0	3/4	3/64	3.840	0.240
B	1	0	1	1	11/16	11/256	3.520	0.220
A	1	0	1	0	5/8	5/128	3.200	0.200
9	1	0	0	1	9/16	9/256	2/880	0.180
8	1	0	0	0	1/2	1/32	2/560	0.160
7	0	1	1	1	7/16	7/256	2.240	0.140
6	0	1	1	0	3/8	3/128	1.920	0.120
5	0	1	0	1	5/16	5/256	1.600	0.100
4	0	1	0	0	1/4	1/64	1/280	0.080
3	0	0	1	1	3/16	3/256	0.960	0.060
2	0	0	1	0	1/8	1/128	0.640	0.040
1	0	0	0	1	1/16	1/256	0.320	0.020
0	0	0	0	0			0	0

*Display Output = VMS Group + VLS Group

Functional Description (Continued)



Note 1: *Pin numbers for the DP8228 system controller, others are INS8080A.

Note 2: Pin 23 of the INS6228 must be tied to +12V through a 1 kΩ resistor to generate the RST 7 instruction when an interrupt is acknowledged as required by the accompanying sample program.

FIGURE 10. ADC0801-INS8080A CPU Interface

SAMPLE PROGRAM FOR *FIGURE 10* ADC0801-INS8080A CPU INTERFACE

```
0038    C3 00 03   RST 7:        JMP  LD DATA
  •        •          •
  •        •          •
0100    21 00 02   START:        LXI H 0200H     ; HL pair will point to
                                                 ; data storage locations
0103    31 00 04   RETURN:       LXI SP 0400H    ; Initialize stack pointer (Note 1)
0106    7D                       MOV A, L        ; Test # of bytes entered
0107    FE 0F                    CPI 0F H        ; If # = 16. JMP to
0109    CA 13 01                 JZ CONT         ; user program
010C    D3 E0                    OUT E0 H        ; Start A/D
010E    FB                       EI              ; Enable interrupt
010F    00         LOOP:         NOP             ; Loop until end of
0110    C3 0F 01                 JMP LOOP        ; conversion
0113       •       CONT:            •
  •        •          •             •
  •        •       (User program to •
  •        •       process data)    •
  •        •          •             •
  •        •          •             •
0300    DB E0      LD DATA:      IN E0 H         ; Load data into accumulator
0302    7 /                      MOV M, A        ; Store data
0303    23                       INX H           ; Increment storage pointer
0304    C3 03 01                 JMP RETURN
```

Note 1: The stack pointer must be dimensioned because a RST 7 instruction pushes the PC onto the stack.

***Note 2:** All address used were arbitrarily chosen*

Functional Description (Continued)

The standard control bus signals of the 8080 $\overline{CS}$, $\overline{RD}$ and $\overline{WR}$) can be directly wired to the digital control inputs of the A/D and the bus timing requirements are met to allow both starting the converter and outputting the data onto the data bus. A bus driver should be used for larger microprocessor systems where the data bus leaves the PC board and/or must drive capacitive loads larger than 100 pF.

4.1.1 Sample 8080A CPU Interfacing Circuitry and Program

The following sample program and associated hardware shown in *Figure 10* may be used to input data from the converter to the INS8080A CPU chip set (comprised of the INS8080A microprocessor, the INS8228 system controller and the INS8224 clock generator). For simplicity, the A/D is controlled as an I/O device, specifically an 8-bit bi-directional port located at an arbitrarily chosen port address, E0. The TRI-STATE output capability of the A/D eliminates the need for a peripheral interface device, however address decoding is still required to generate the appropriate $\overline{CS}$ for the converter.

It is important to note that in systems where the A/D converter is 1-of-8 or less I/O mapped devices, no address decoding circuitry is necessary. Each of the 8 address bits (A0 to A7) can be directly used as $\overline{CS}$ inputs—one for each I/O device.

4.1.2 INS8048 Interface

The INS8048 interface technique with the ADC0801 series (see *Figure 11*) is simpler than the 8080A CPU interface. There are 24 I/O lines and three test input lines in the 8048. With these extra I/O lines available, one of the I/O lines (bit 0 of port 1) is used as the chip select signal to the A/D, thus eliminating the use of an external address decoder. Bus control signals $\overline{RD}$, $\overline{WR}$ and $\overline{INT}$ of the 8048 are tied directly to the A/D. The 16 converted data words are stored at on-chip RAM locations from 20 to 2F (Hex). The $\overline{RD}$ and $\overline{WR}$ signals are generated by reading from and writing into a dummy address, respectively. A sample interface program is shown below.

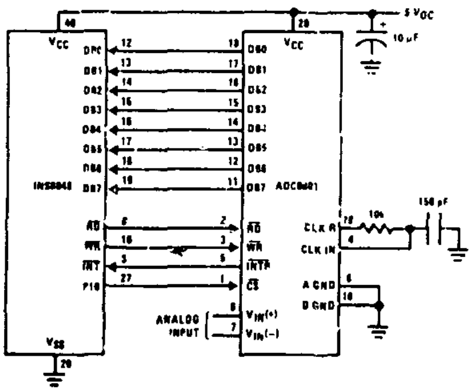


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FIGURE 11. INS8048 Interface

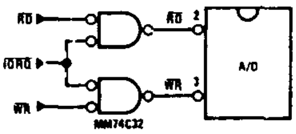
SAMPLE PROGRAM FOR *FIGURE 11* INS8048 INTERFACE

```
04 10                 JMP    10H        ; Program starts at addr 10
                      ORG    3H
04 50                 JMP    50H        ; Interrupt jump vector
                      ORG    10H        ; Main program
99 FE                 ANL    P1, #0FEH  ; Chip select
81                    MOVX   A, @R1     ; Read in the 1st data
                                        ; to reset the intr
89 01     START:      ORL    P1, #1     ; Set port pin high
B8 20                 MOV    R0, #20H   ; Data address
B9 FF                 MOV    R1, #0FFH  ; Dummy address
BA 10                 MOV    R2, #10H   ; Counter for 16 bytes
23 FF     AGAIN:      MOV    A, #0FFH   ; Set ACC for intr loop
99 FE                 ANL    P1, #0FEH  ; Send CS (bit 0 of P1)
91                    MOVX   @R1, A     ; Send WR out
05                    EN     I          ; Enable interrupt
96 21     LOOP:       JNZ    LOOP       ; Wait for interrupt
EA 1B                 DJNZ   R2, AGAIN  ; If 16 bytes are read
00                    NOP               ; go to user's program
00                    NOP
                      ORG    50H
81        INDATA:     MOVX   A, @R1     ; Input data, CS still low
A0                    MOV    @R0, A     ; Store in memory
18                    INC    R0         ; Increment storage counter
89 01                 ORL    P1, #1     ; Reset CS signal
27                    CLR    A          ; Clear ACC to get out of
93                    RETR              ; the interrupt loop
```

Functional Description (Continued)

4.2 Interfacing the Z-80

The Z-80 control bus is slightly different from that of the 8080. General $\overline{RD}$ and $\overline{WR}$ strobes are provided and separate memory request, $\overline{MREQ}$, and I/O request, $\overline{IORQ}$, signals are used which have to be combined with the generalized strobes to provide the equivalent 8080 signals. An advantage of operating the A/D in I/O space with the Z-80 is that the CPU will automatically insert one wait state (the $\overline{RD}$ and $\overline{WR}$ strobes are extended one clock period) to allow more time for the I/O devices to respond. Logic to map the A/D in I/O space is shown in *Figure 13*.



TL/H/5671-23

FIGURE 13. Mapping the A/D as an I/O Device for Use with the Z-80 CPU

Additional I/O advantages exist as software DMA routines are available and use can be made of the output data transfer which exists on the upper 8 address lines (A8 to A15) during I/O input instructions. For example, MUX channel selection for the A/D can be accomplished with this operating mode.

4.3 Interfacing 6800 Microprocessor Derivatives (6502, etc.)

The control bus for the 6800 microprocessor derivatives does not use the $\overline{RD}$ and $\overline{WR}$ strobe signals. Instead it employs a single R/$\overline{W}$ line and additional timing, if needed, can be derived fom the $\phi 2$ clock. All I/O devices are memory mapped in the 6800 system, and a special signal, VMA, indicates that the current address is valid. *Figure 14* shows an interface schematic where the A/D is memory mapped in the 6800 system. For simplicity, the $\overline{CS}$ decoding is shown using ½ DM8092. Note that in many 6800 systems, an already decoded $\overline{4/5}$ line is brought out to the common bus at pin 21. This can be tied directly to the $\overline{CS}$ pin of the A/D, provided that no other devices are addressed at HX ADDR: 4XXX or 5XXX.

The following subroutine performs essentially the same function as in the case of the 8080A interface and it can be called from anywhere in the user's program.

In *Figure 15* the ADC0801 series is interfaced to the M6800 microprocessor through (the arbitrarily chosen) Port B of the MC6820 or MC6821 Peripheral Interface Adapter, (PIA). Here the $\overline{CS}$ pin of the A/D is grounded since the PIA is already memory mapped in the M6800 system and no $\overline{CS}$ decoding is necessary. Also notice that the A/D output data lines are connected to the microprocessor bus under program control through the PIA and therefore the A/D $\overline{RD}$ pin can be grounded.

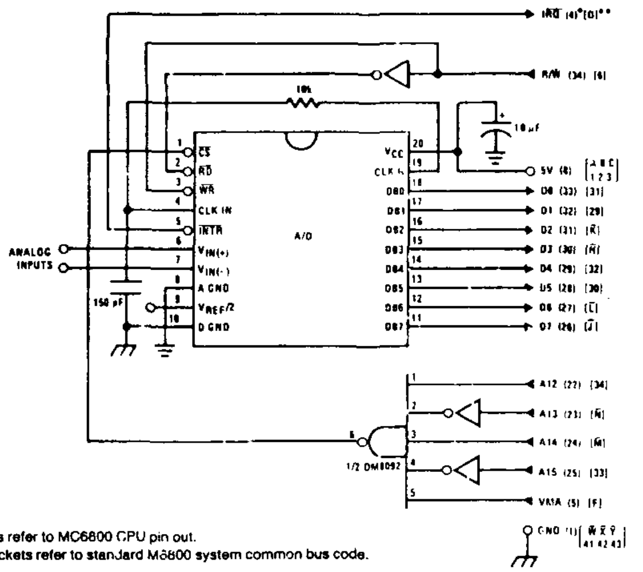
A sample interface program equivalent to the previous one is shown below *Figure 15*. The PIA Data and Control Registers of Port B are located at HEX addresses 8006 and 8007, respectively.

5.0 GENERAL APPLICATIONS

The following applications show some interesting uses for the A/D. The fact that one particular microprocessor is used is not meant to be restrictive. Each of these application circuits would have its counterpart using any microprocessor that is desired.

5.1 Multiple ADC0801 Series to MC6800 CPU Interface

To transfer analog data from several channels to a single microprocessor system, a multiple converter scheme presents several advantages over the conventional multiplexer single-converter approach. With the ADC0801 series, the differential inputs allow individual span adjustment for each channel. Furthermore, all analog input channels are sensed simultaneously, which essentially divides the microprocessor's total system servicing time by the number of channels, since all conversions occur simultaneously. This scheme is shown in *Figure 16*.



Note 1: Numbers in parentheses refer to MC6800 CPU pin out.
Note 2: Number or letters in brackets refer to standard M6800 system common bus code.

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FIGURE 14. ADC0801-MC6800 CPU Interface

Functional Description (Continued)

SAMPLE PROGRAM FOR *FIGURE 14* ADC0801-MC6800 CPU INTERFACE

```
0010   DF 36      DATAIN   STX    TEMP2     ; Save contents of X
0012   CE 00 2C            LDX    #$002C    ; Upon IRQ low CPU
0015   FF FF F8            STX    $FFF8     ; jumps to 002C
0018   B7 50 00            STAA   $5000     ; Start ADC0801
001B   0E                  CLI
001C   3E         CONVRT   WAI              ; Wait for interrupt
001D   DE 34               LDX    TEMP1
001F   8C C2 0F            CPX    #$020F    ; Is final data stored?
0022   27 14               BEQ    ENDP
0024   B7 50 00            STAA   $5000     ; Restarts ADC0801
0027   08                  INX
0028   DF 34               STX    TEMP1
002A   20 F0               BRA    CONVRT
002C   DE 34      INTRPT   LDX    TEMP1
002E   B6 50 00            LDAA   $5000     ; Read data
0031   A7 00               STAA   X         ; Store it at X
0033   3B                  RTI
0034   02 00      TEMP1    FDB    $0200     ; Starting address for
                                            ; data storage
0036   00 00      TEMP2    FDB    $0000
0038   CE 02 00   ENDP     LDX    #$0200    ; Reinitialize TEMP1
003B   DF 34               STX    TEMP1
003D   DE 36               LDX    TEMP2
003F   39                  RTS              ; Return from subroutine
                                            ; To user's program
```

Note 1: In order for the microprocessor to service subroutines and interrupts, the stack pointer *must be dimensioned* in the user's program.

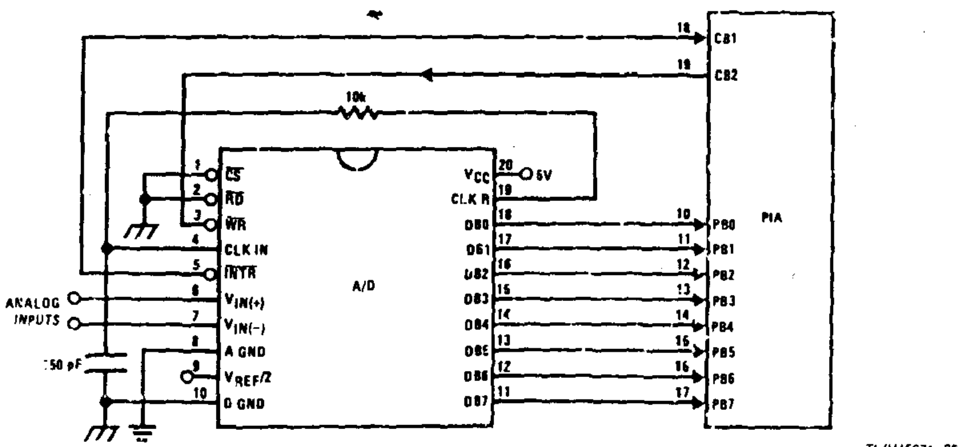


FIGURE 15. ADC0801-MC6820 PIA Interface

Functional Description (Continued)

SAMPLE PROGRAM FOR *FIGURE 15* ADC0801–MC6820 PIA INTERFACE

```
0010   CE 00 38   DATAIN   LDX    #$0038    ; Upon IRQ low CPU
0013   FF FF F8            STX    $FFF8     ; jumps to 0038
0016   B6 80 06            LDAA   PIAORB    ; Clear possible IRQ flags
0019   4F                  CLRA
001A   B7 80 07            STAA   PIACRB
001D   B7 80 06            STAA   PIAORB    ; Set Port B as input
0020   0E                  CLI
0021   C6 34               LDAB   #$34
0023   86 3D               LDAA   #$3D
0025   F7 80 07   CONVRT   STAB   PIACRB    ; Starts ADC0801
0028   B7 80 07            STAA   PIACRB
002B   3E                  WAI              ; Wait for interrupt
002C   DE 40               LDX    TEMP1
002E   8C 02 0F            CPX    #$020F    ; Is final data stored?
0031   27 0F               BEQ    ENDP
0033   08                  INX
0034   DF 40               STX    TEMP1
0036   20 ED               BRA    CONVRT
0038   DE 40      INTRPT   LDX    TEMP1
003A   B6 80 06            LDAA   PIAORB    ; Read data in
003D   A7 00               STAA   X         ; Store it at X
003F   3B                  RTI
0040   02 00      TEMP1    FDB    $0200     ; Starting address for
                                            ; data storage
0042   CE 02 00   ENDP     LDX    #$0200    ; Reinitialize TEMP1
0045   DF 40               STX    TEMP1
0047   39                  RTS              ; Return from subroutine
                  PIAORB   EQU    $8006     ; To user's program
                  PIACRB   EQU    $8007
```

The following schematic and sample subroutine (DATA IN) may be used to interface (up to) 8 ADC0801's directly to the MC6800 CPU. This scheme can easily be extended to allow the interface of more converters. In this configuration the converters are (arbitrarily) located at HEX address 5000 in the MC6800 memory space. To save components, the clock signal is derived from just one RC pair on the first converter. This output drives the other A/Ds.

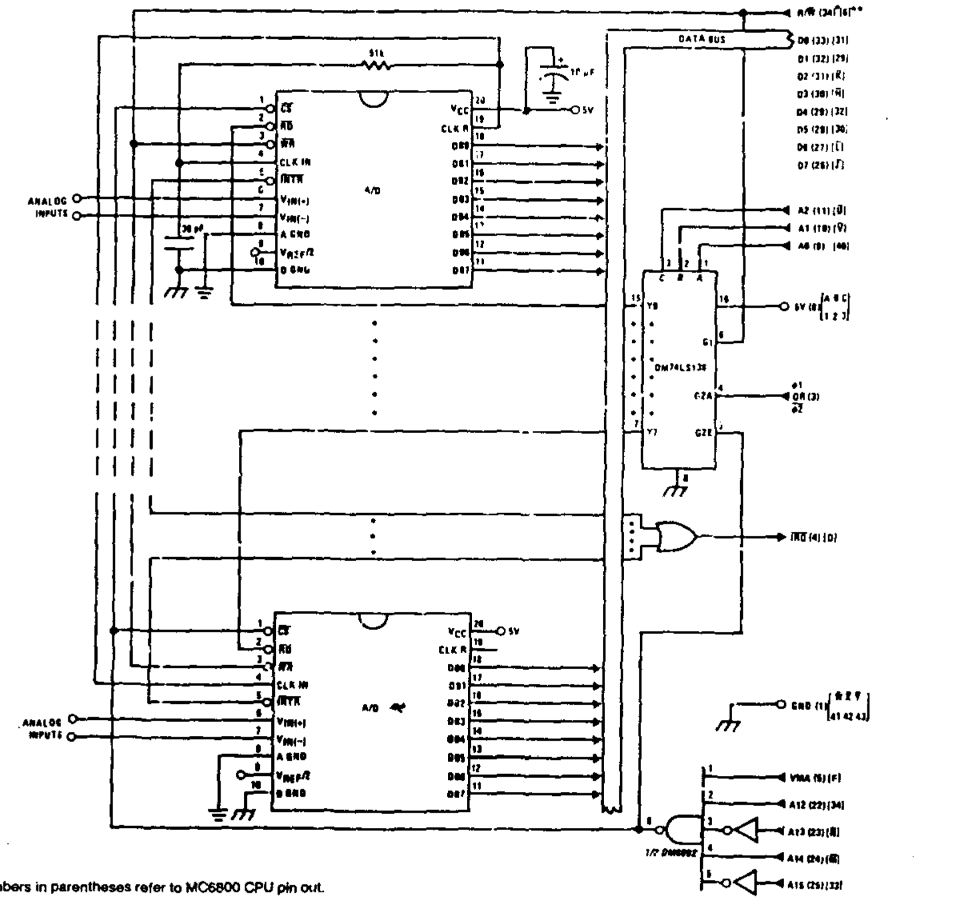
All the converters are started simultaneously with a STORE instruction at HEX address 5000. Note that any other HEX address of the form 5XXX will be decoded by the circuit, pulling all the $\overline{CS}$ inputs low. This can easily be avoided by using a more definitive address decoding scheme. All the interrupts are ORed together to insure that all A/Ds have completed their conversion before the microprocessor is interrupted.

The subroutine, DATA IN, may be called from anywhere in the user's program. Once called, this routine initializes the CPU, starts all the converters simultaneously and waits for the interrupt signal. Upon receiving the interrupt, it reads the converters (from HEX addresses 5000 through 5007) and stores the data successively at (arbitrarily chosen) HEX addresses 0200 to 0207, before returning to the user's program. All CPU registers then recover the original data they had before servicing DATA IN.

5.2 Auto-Zeroed Differential Transducer Amplifier and A/D Converter

The differential inputs of the ADC0801 series eliminate the need to perform a differential to single ended conversion for a differential transducer. Thus, one op amp can be eliminated since the differential to single ended conversion is provided by the differential input of the ADC0801 series. In general, a transducer preamp is required to take advantage of the full A/D converter input dynamic range.

Functional Description (Continued)



Note 1: Numbers in parentheses refer to MC6800 CPU pin out.

Note 2: Numbers of letters in brackets refer to standard M6800 system common bus code.

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FIGURE 16. Interfacing Multiple A/Ds in an MC6800 System

SAMPLE PROGRAM FOR *FIGURE 16* INTERFACING MULTIPLE A/Ds IN AN MC6800 SYSTEM

ADDRESS	HEX CODE		MNEMONICS		COMMENTS
0010	DF 44	DATAIN	STX	TEMP	; Save Contents of X
0012	CE 00 2A		LDX	#$002A	; Upon IRQ LOW CPU
0015	FF FF F8		STX	$FFF8	; Jumps to 002A
0018	B7 50 00		STAA	$5000	; Starts all A/D's
001B	0E		CLI		
001C	3E		WAI		; Wait for interrupt
001D	CE 50 00		LDX	#$5000	
0020	DF 40		STX	INDEX1	; Reset both INDEX
0022	CE 02 00		LDX	#$0200	; 1 and 2 to starting
0025	DF 42		STX	INDEX2	; addresses
0027	DE 44		LDX	TEMP	
0029	39		RTS		; Return from subroutine
002A	DE 40	INTRPT	LDX	INDEX1	; INDEX1 → X
002C	A6 00		LDAA	X	; Read data in from A/D at X
002E	08		INX		; Increment X by one
002F	DF 40		STX	INDEX1	; X → INDEX1
0031	DE 42		LDX	INDEX2	; INDEX2 → X

Functional Description (Continued)

SAMPLE PROGRAM FOR *FIGURE 16* INTERFACING MULTIPLE A/Ds IN AN MC6800 SYSTEM

ADDRESS	HEX CODE	MNEMONICS			COMMENTS
0033	A7 00		STAA	X	; Store data at X
0035	8C 02 07		CPX	#$0207	; Have all A/D's been read?
0038	27 05		BEQ	RETURN	; Yes: branch to RETURN
003A	08		INX		; No: increment X by one
003B	DF 42		STX	INDEX2	; X → INDEX2
003D	20 EB		BRA	INTRPT	; Branch to 002A
003F	3B	RETURN	RTI		
0040	50 00	INDEX1	FDB	$5000	; Starting address for A/D
0042	02 00	INDEX2	FDB	$0200	; Starting address for data storage
0044	00 00	TEMP	FDB	$0000	

Note 1: In order for the microprocessor to service subroutines and interrupts, the stack pointer must be dimensioned in the user's program

For amplification of DC input signals, a major system error is the input offset voltage of the amplifiers used for the preamp. *Figure 17* is a gain of 100 differential preamp whose offset voltage errors will be cancelled by a zeroing subroutine which is performed by the INS8080A microprocessor system. *The total allowable input offset voltage error* for this preamp is only 50 μV for ¼ LSB error. This would obviously require very precise amplifiers. The expression for the differential output voltage of the preamp is:

$$V_O = \underbrace{[V_{IN}(+) - V_{IN}(-)]}_{\text{SIGNAL}} \underbrace{\left[1 + \frac{2R2}{R1}\right]}_{\text{GAIN}} +$$

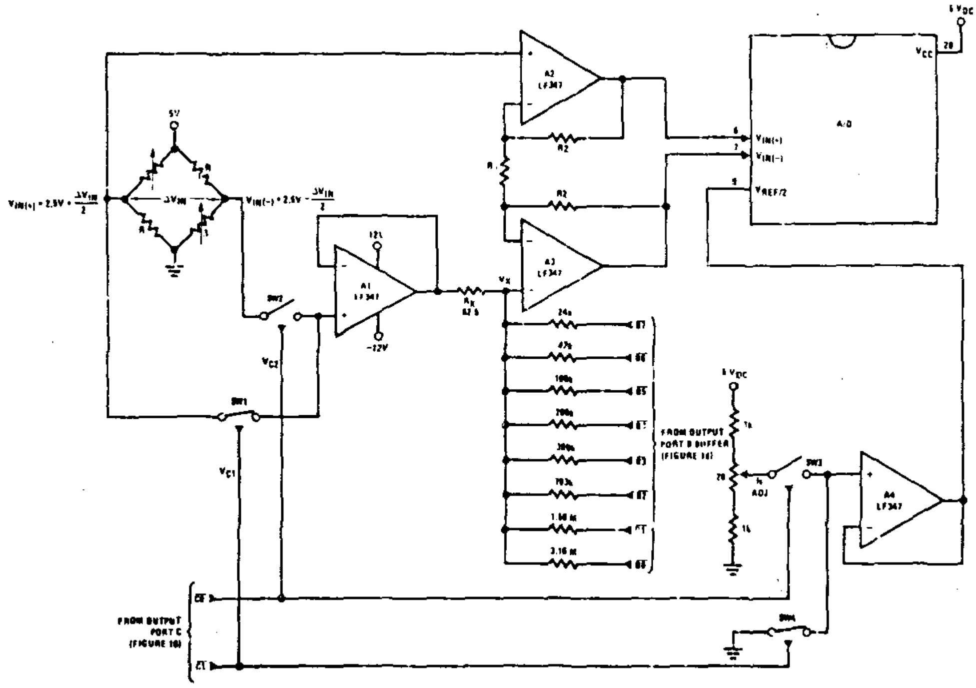
$$\underbrace{(V_{OS_2} - V_{OS_1} - V_{OS_3} \pm I_X R_X)}_{\text{DC ERROR TERM}} \underbrace{\left(1 + \frac{2R2}{R1}\right)}_{\text{GAIN}}$$

where I_X is the current through resistor R_X. All of the offset ***error terms can be cancelled by making*** $\pm I_X R_X = V_{OS1} + V_{OS3} - V_{OS2}$. **This is the principle of this auto-zeroing** scheme.

The INS8080A uses the 3 I/O ports of an INS8255 Programable Peripheral Interface (PPI) to control the auto zeroing and input data from the ADC0801 as shown in *Figure 18*. The PPI is programmed for basic I/O operation (mode 0) with Port A being an input port and Ports B and C being output ports. *Two bits of Port C are used to alternately open* or close the 2 switches at the input of the preamp. Switch SW1 is closed to force the preamp's differential input to be zero during the zeroing subroutine and then opened and SW2 is then closed for conversion of the actual differential input signal. Using 2 switches in this manner eliminates concern for the ON resistance of the switches as they must *conduct only the input bias current of the input amplifiers.*

Output Port B is used as a successive approximation register by the 8080 and the binary scaled resistors in series with each output bit create a D/A converter. During the zeroing subroutine, the voltage at V_x increases or decreases as required to make the differential output voltage equal to zero. This is accomplished by ensuring that the voltage at the output of A1 is approximately 2.5V so that a logic "1" (5V) on any output of Port B will source current into node V_X thus raising the voltage at V_X and making the output differential more negative. Conversely, a logic "0" (0V) will pull current out of node V_X and decrease the voltage, causing the differential output to become more positive. For the resistor values shown, V_X can move ±12 mV with a resolution of 50 μV, which will null the offset error term to ¼ LSB of full-scale for the ADC0801. It is important that the voltage levels *that drive the auto-zero resistors be constant. Also, for symmetry,* a logic swing of 0V to 5V is convenient. To achieve this, a CMOS buffer is used for the logic output signals of Port B and this CMOS package is powered with a stable 5V source. Buffer amplifier A1 is necessary so that it can source or sink the D/A output current.

Functional Description (Continued)



Note 1: R2 = 49.5 R1

Note 2: Switches are LMC13334 CMOS analog switches.

Note 3: The 9 resistors used in the auto-zero section can be ±5% tolerance.

FIGURE 17. Gain of 100 Differential Transducer Preamp

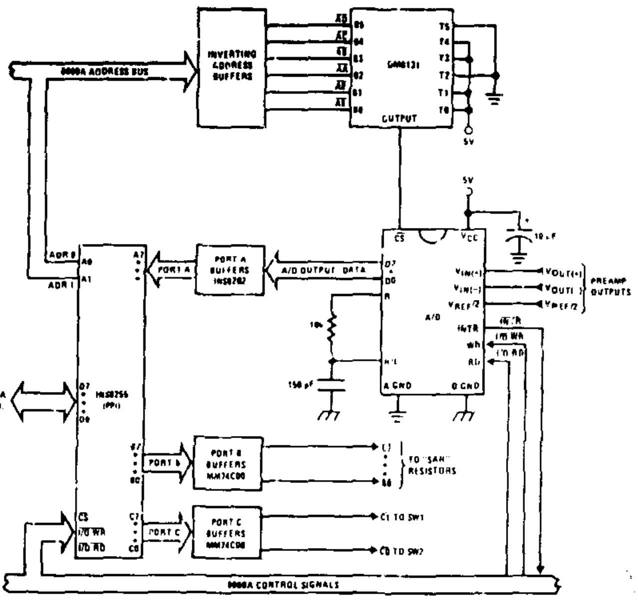


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FIGURE 18. Microprocessor Interface Circuitry for Differential Preamp

A flow chart for the zeroing subroutine is shown in *Figure 19*. It must be noted that the ADC0801 series will output an all zero code when it converts a negative input $[V_{IN}(-) \geq V_{IN}(+)]$. Also, a logic inversion exists as all of the I/O ports are buffered with inverting gates.

Basically, if the data read is zero, the differential output voltage is negative, so a bit in Port B is cleared to pull V_X more negative which will make the output more positive for the next conversion. If the data read is not zero, the output voltage is positive so a bit in Port B is set to make V_X more positive and the output more negative. This continues for 8 approximations and the differential output eventually converges to within 5 mV of zero.

The actual program is given in *Figure 20*. All addresses used are compatible with the BLC 80/10 microcomputer system. In particular:

Port A and the ADC0801 are at port address E4

Port B is at port address E5

Port C is at port address E6

PPI control word port is at port address E7

Program Counter automatically goes to ADDR:3C3D upon acknowledgement of an interrupt from the ADC0801

5.3 Multiple A/D Converters in a Z-80 Interrupt Driven Mode

In data acquisition systems where more than one A/D converter (or other peripheral device) will be interrupting program execution of a microprocessor, there is obviously a need for the CPU to determine which device requires servicing. *Figure 21* and the accompanying software is a method of determining which of 7 ADC0801 converters has completed a conversion ($\overline{INTR}$ asserted) and is requesting an interrupt. This circuit allows starting the A/D converters in any sequence, but will input and store valid data from the converters with a priority sequence of A/D 1 being read first, A/D 2 second, etc., through A/D 7 which would have the lowest priority for data being read. Only the converters whose $\overline{INT}$ is asserted will be read.

The key to decoding circuitry is the DM74LS373, 8-bit D type flip-flop. When the Z-80 acknowledges the interrupt, the program is vectored to a data input Z-80 subroutine. This subroutine will read a peripheral status word from the DM74LS373 which contains the logic state of the $\overline{INTR}$ outputs of all the converters. Each converter which initiates an interrupt will place a logic "0" in a unique bit position in the status word and the subroutine will determine the identity of the converter and execute a data read. An identifier word (which indicates which A/D the data came from) is stored in the next sequential memory location above the location of the data so the program can keep track of the identity of the data entered.

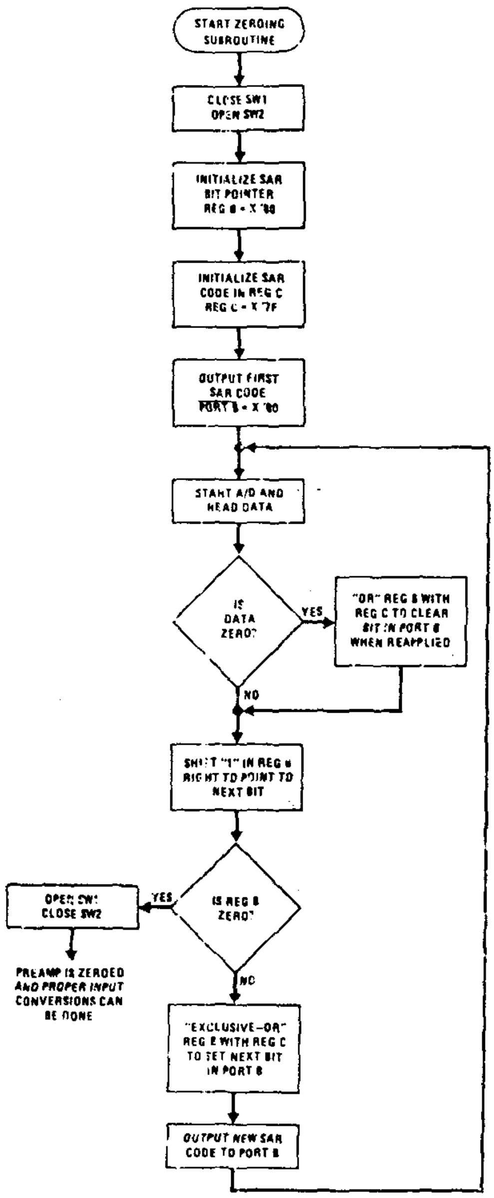

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FIGURE 19. Flow Chart for Auto-Zero Routine

```
3D00   3E90     MVI 90
3D02   D3E7     Out Control Port                                  ; Program PPI
3D04   2601     MVI H C1           Auto-Zero Subroutine
3D06   7C       MOV A,H
3D07   D3E6     OUT C                                             ; Close SW1 open SW2
3D09   0680     MVI B 80                                          ; Initialize SAR bit pointer
3D0B   3E7F     MVI A 7F                                          ; Initialize SAR code
3D0D   4F       MOV C,A            Return
3D0E   D3E5     OUT B                                             ; Port B = SAR code
3D10   31AA3D   LXI SP 3DAA        Start                          ; Dimension stack pointer
3D13   D3E4     OUT A                                             ; Start A/D
3D15   FB       IE
3D16   00       NOP                Loop                           ; Loop until INT asserted
3D17   C3163D   JMP Loop
3D1A   7A       MOV A,D            Auto-Zero
3D1B   C600     ADI 00
3D1D   CA2D3D   JZ Set C                                          ; Test A/D output data for zero
3D20   78       MOV A,B            Shift B
3D21   F600     ORI 00                                            ; Clear carry
3D23   1F       RAR                                               ; Shift "1" in B right one place
3D24   FE00     CPI 00                                            ; Is B zero? If yes last
3D26   CA373D   JZ Done                                           ; approximation has been made
3D29   47       MOV B,A
3D2A   C3333D   JMP New C
3D2D   79       MOV A,C            Set C
3D2E   B0       ORA B                                             ; Set bit in C that is in same
3D2F   4F       MOV C,A                                           ; position as "1" in B
3D30   C3203D   JMP Shift B
3D33   A9       XRA C              New C                          ; Clear bit in C that is in
3D34   C30D3D   JMP Return                                        ; same position as "1" in B
3D37   47       MOV B,A            Done                           ; then output new SAR code.
3D38   7C       MOV A,H                                           ; Open SW1, close SW2 then
3D39   EE03     XRI 03                                            ; proceed with program. Preamp
3D3B   D3E6     OUT C                                             ; is now zeroed.
3D3D            •                  Normal
                •
                •
                Program for processing
                proper data values
3C3D   DBE4     IN A               Read A/D Subroutine            ; Read A/D data
3C3F   EEFF     XRI FF                                            ; Invert data
3C41   57       MOV D,A
3C42   78       MOV A,B                                           ; Is B Reg = 0? If not stay
3C43   E6FF     ANI FF                                            ; in auto zero subroutine
3C45   C21A3D   JNZ Auto-Zero
3C48   C33D3D   JMP Normal
```

Note: All numerical values are hexadecimal representations.

FIGURE 20. Software for Auto-Zeroed Differential A/D

5.3 Multiple A/D Converters in a Z-80® Interrupt Driven Mode (Continued)

The following notes apply:

1) It is assumed that the CPU automatically performs a RST 7 instruction when a valid interrupt is *acknowledged* (CPU is in interrupt mode 1). Hence, the subroutine starting address of X0038.

2) The address bus from the Z-80 and the data bus to the Z-80 are assumed to be inverted by bus drivers.

3) A/D data and identifying words will be stored in sequential memory locations starting at the arbitrarily chosen address X 3E00.

4) The stack pointer must be dimensioned in the main program as the RST 7 instruction automatically pushes the PC onto the stack and the subroutine uses an additional 6 stack addresses.

5) The peripherals of concern are mapped into I/O space with the following port assignments:

HEX PORT ADDRESS	PERIPHERAL
00	MM74C374 8-bit flip-flop
01	A/D 1
02	A/D 2
03	A/D 3
04	A/D 4
05	A/D 5
06	A/D 6
07	A/D 7

This port address also serves as the A/D identifying word in the program.

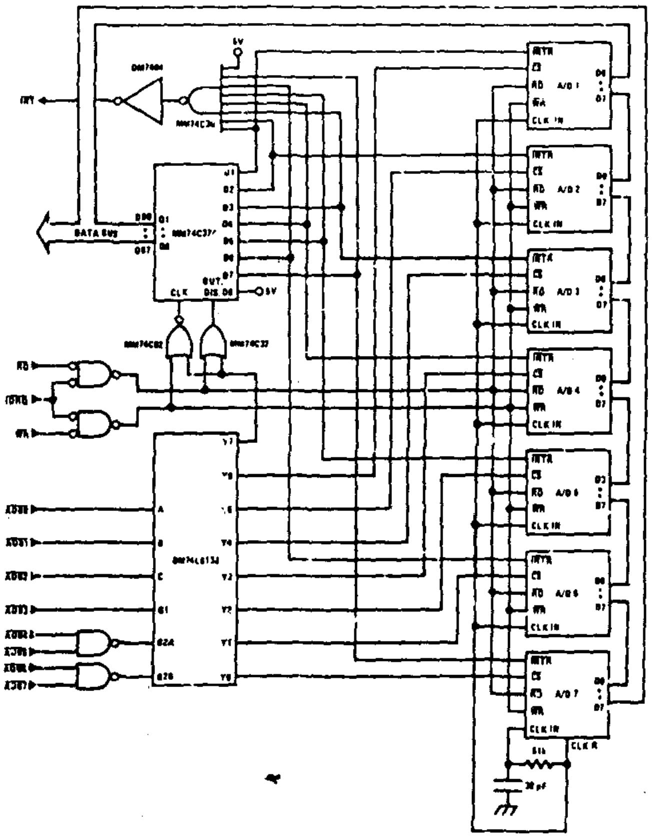

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FIGURE 21. Multiple A/Ds with Z-80 Type Microprocessor

INTERRUPT SERVICING SUBROUTINE

LOC	OBJ CODE		SOURCE STATEMENT	COMMENT
0038	E5		PUSH HL	; Save contents of all registers affected by
0039	C5		PUSH BC	; this subroutine.
003A	F5		PUSH AF	; Assumed INT mode 1 earlier set.
003B	21 00 3E		LD (HL), X3E00	; Initialize memory pointer where data will be stored.
003E	OE 01		LD C, X01	; C register will be port ADDR of A/D converters.
0040	D300		OUT X00, A	; Load peripheral status word into 8-bit latch.
0042	DB00		IN A, X00	; Load status word into accumulator.
0044	47		LD B, A	; Save the status word.
0045	79	TEST	LD A, C	; Test to see if the status of all A/D's have
0046	FE 08		CP, X08	; been checked. If so, exit subroutine
0048	CA 60 00		JPZ, DONE	
004B	78		LD A, B	; Test a single bit in status word by looking for
004C	1F		RRA	; a "1" to be rotated into the CARRY (an $\overline{INT}$
004D	47		LD B, A	; is loaded as a "1"). If CARRY is set then load
004E	DA 5500		JPC, LOAD	; contents of A/D at port ADDR in C register.
0051	0C	NEXT	INC C	; If CARRY is not set, increment C register to point
0052	C3 4500		JP, TEST	; to next A/D, then test next bit in status word.
0055	ED 78	LOAD	IN A, (C)	; Read data from interrupting A/D and invert
0057	EE FF		XOR FF	; the data.
0059	77		LD (HL), A	; Store the data
005A	2C		INC L	
005B	71		LD (HL), C	; Store A/D identifier (A/D port ADDR).
005C	2C		INC L	
005D	C3 51 00		JP, NEXT	; Test next bit in status word.
0060	F1	DONE	POP AF	; Re-establish all registers as they were
0061	C1		POP BC	; before the interrupt.
0062	E1		POP HL	
0063	C9		RET	; Return to original program

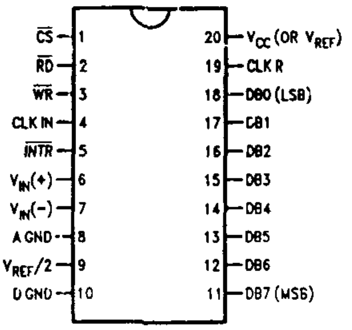
Ordering Information

TEMP RANGE		0°C TO 70°C	0°C TO 70°C	0°C TO 70°C	−40°C TO +85°C
ERROR	±1/4 Bit Adjusted				ADC0801LCN
	±1/2 Bit Unadjusted	ADC0802LCWM	ADC0802LCV		ADC0802LCN
	±1/2 Bit Adjusted	ADC0803LCWM	ADC0803LCV		ADC0803LCN
	±1 Bit Unadjusted	ADC0804LCWM	ADC0804LCV	ADC0804LCN	ADC0805LCN
PACKAGE OUTLINE		M20B—Small Outline	V20A—Chip Carrier	N20A—Molded DIP	

TEMP RANGE		−40°C TO +85°C	−55°C TO +125°C
ERROR	±1/4 Bit Adjusted	ADC0801LCJ	ADC0801LJ
	±1/2 Bit Unadjusted	ADC0802LCJ	ADC0802LJ
	±1/2 Bit Adjusted	ADC0803LCJ	
	±1 Bit Unadjusted	ADC0804LCJ	
PACKAGE OUTLINE		J20A—Cavity DIP	J20A—Cavity DIP

Connection Diagrams

ADC080X
Dual-In-Line and Small Outline (SO) Packages



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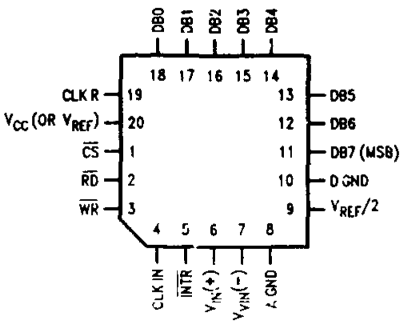
ADC080X
Molded Chip Carrier (PCC) Package



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See Ordering Information